

# **a LIGHTWAVE<sup>®</sup>**

## **LiveWebcast**

### **How to Make Designing Photonic Integrated Chips Accessible and Affordable**

September 16, 2014

# Your Hosts

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**Stephen Hardy**  
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Associate Publisher  
LIGHTWAVE



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General Manager and Principal  
7Pennies Consulting

# Today's Speakers

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Coordinator  
JePPIX



**Twan Korthorst**  
CEO  
Phoenix Software



**Chris Cone**  
Product Marketing  
Manager - Pyxis  
Mentor Graphics

# Today's Speakers

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General Manager  
Bright Photonics



**Arne Leinse**  
Project-/Account Manager &  
Vice President  
LioniX



# How to Make Designing Photonics Integrated Chips Accessible and Affordable

16-Sep-2014



# Agenda

- Introduction on PICs
- Multi-Project Wafer (MPW) shuttle for Photonics
- Photonic Process Design Kits (PDK)
- Choosing between different material systems for PICs
- Packaging, scaling to full production, and IP
- Conclusions

- Sponsors:

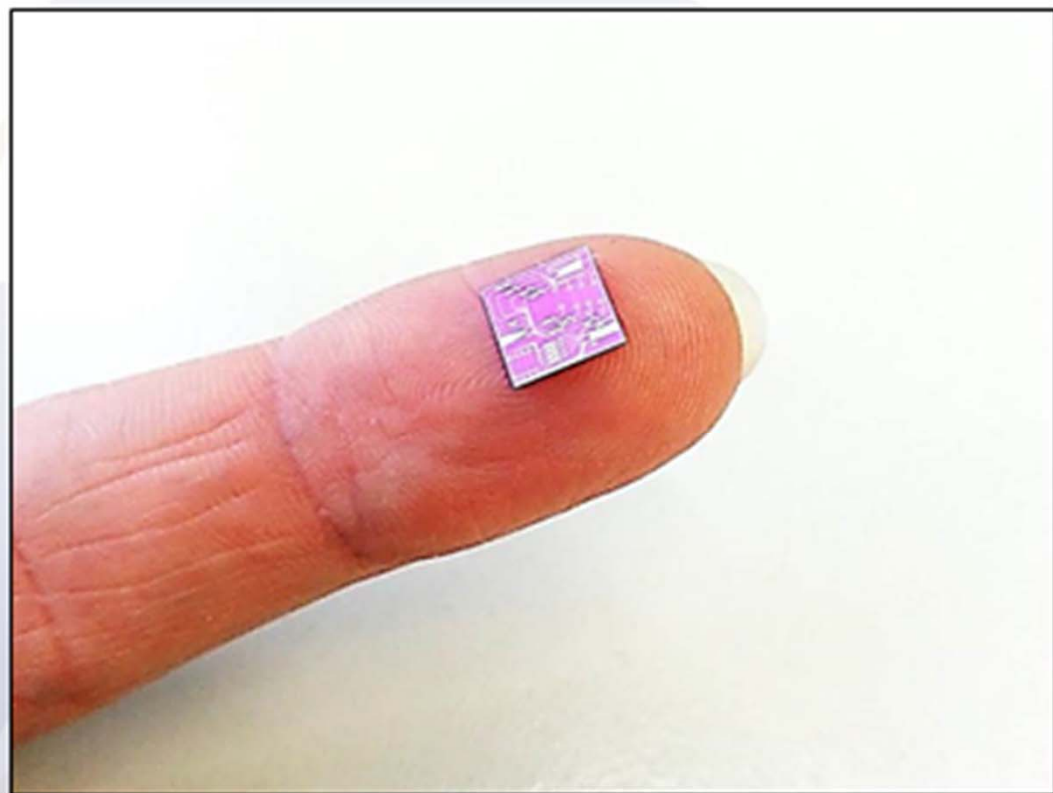


- Organizers:



# Introduction to photonic ICs

- What is inside of photonic ICs?



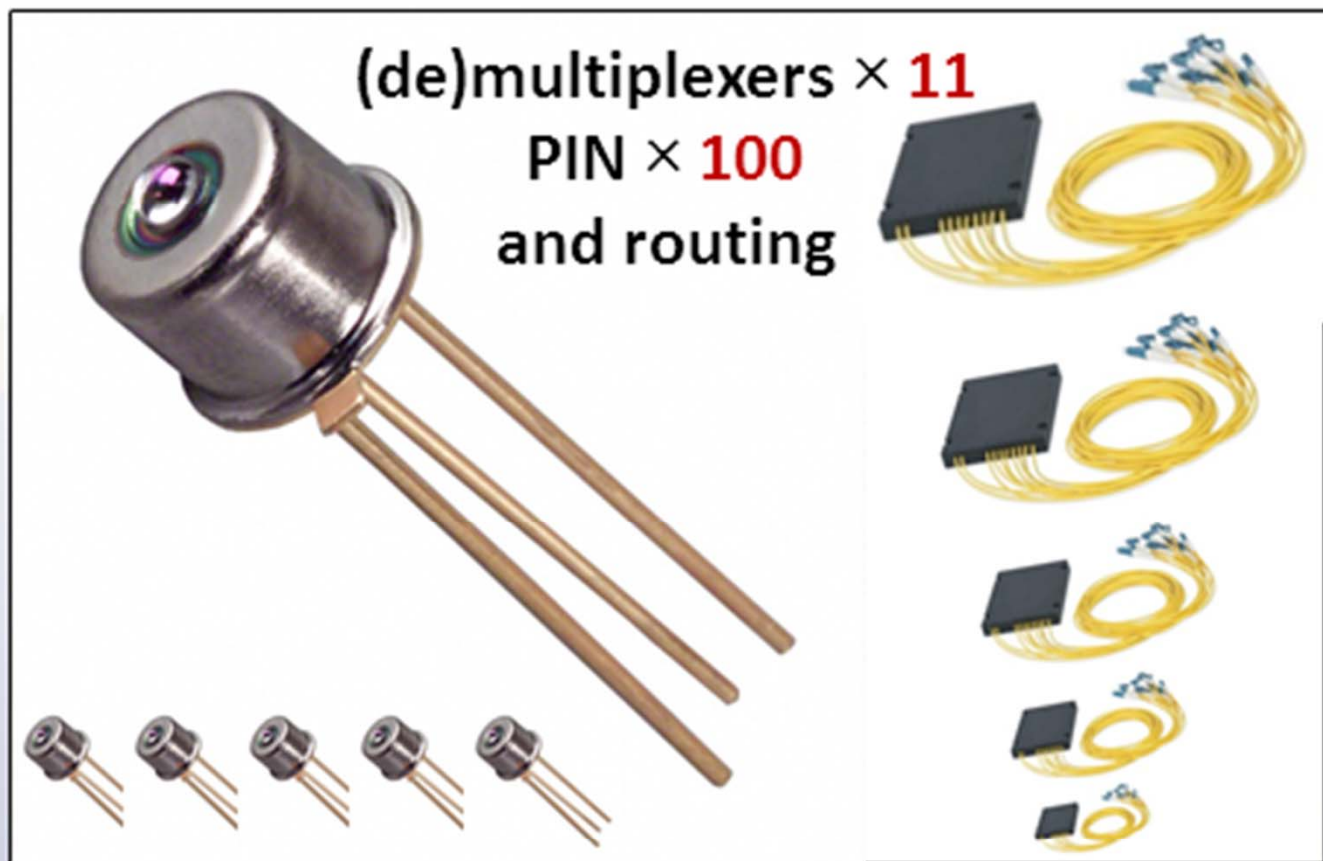
- light propagation

- amplification and light generation

- fast modulation

# Introduction to photonic ICs

- What is inside of photonic ICs?



**conventional**



Single Photonic  
Integrated Circuit



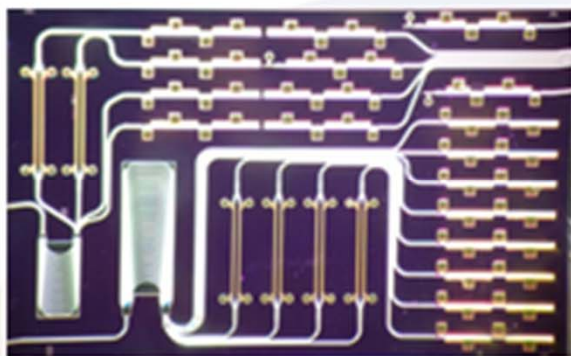
6 mm  $\times$  8 mm  
FBG sensor unit

**vs. integrated**

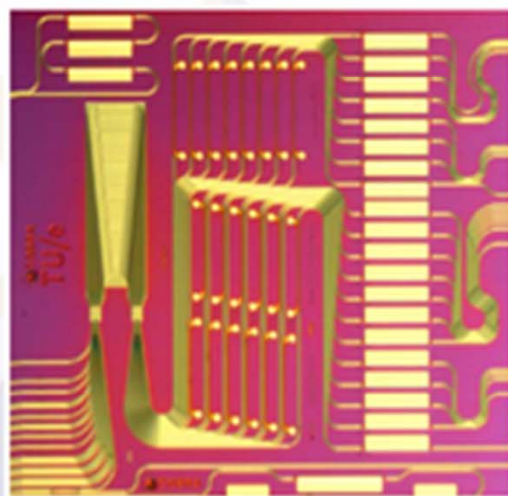


# Application specific photonic ICs

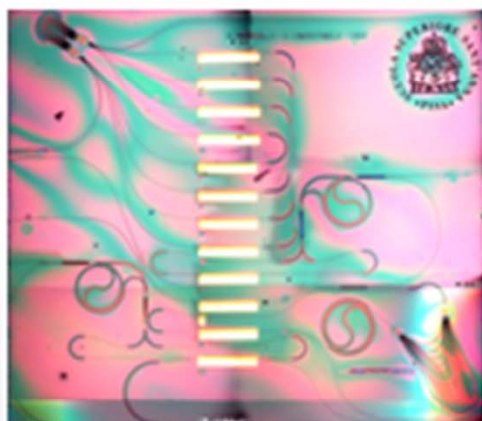
Fiber to the Home  
Wireless



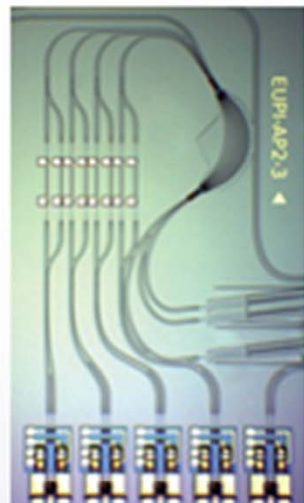
Medical  
Bio-imaging



Datacom  
Switching

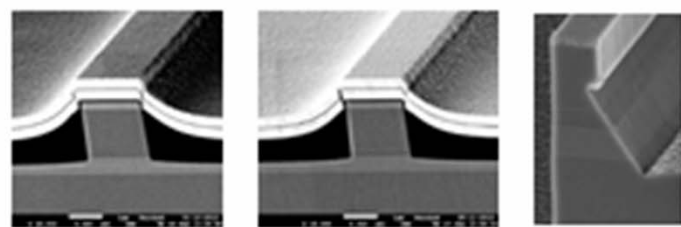
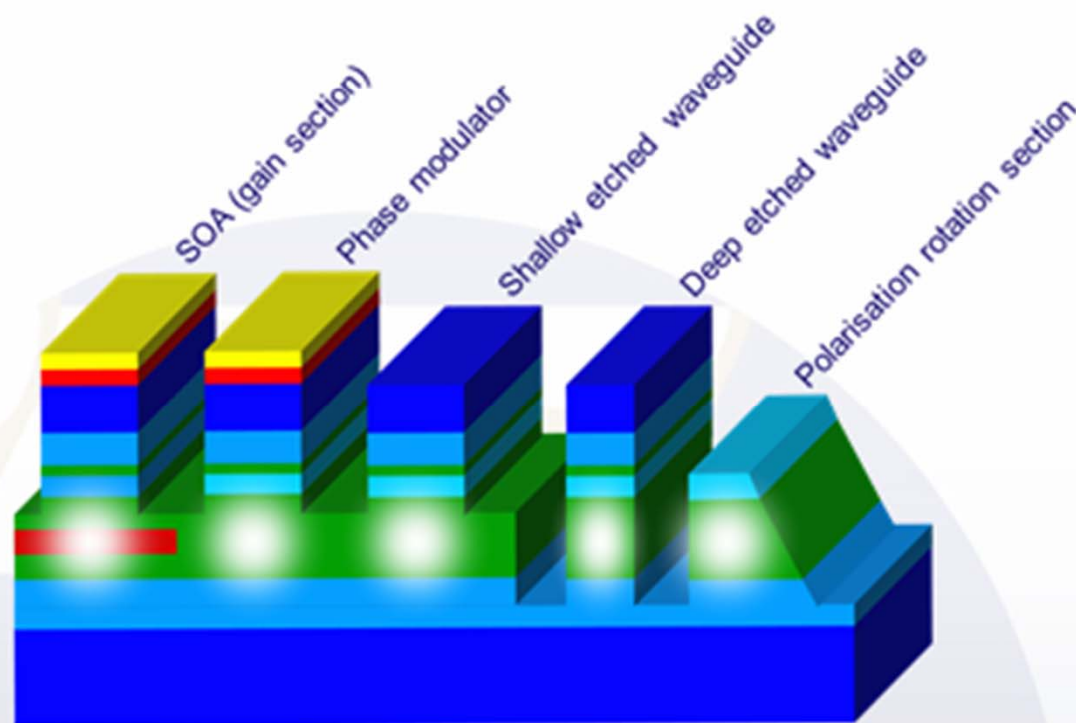


Sensor  
Readouts

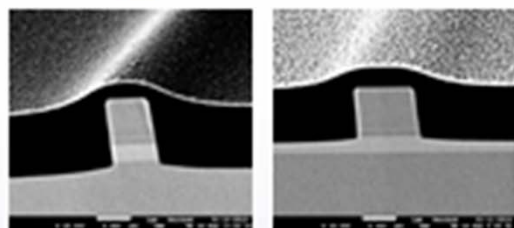


- Application driving technology ?
  - Too expensive, need for high volume market!
  - Fragmentation, long-time investment

# Generic foundry model



**Building blocks!**



- **Solution:** generic technology!
  - Cost **sharing**, application separated from technology development, **fast** prototyping
  - Verified components (building blocks): **reduction** of design time and number of fab cycles

# Generic technology: building blocks



MMI-couplers and filters



MMI-reflectors



AWG-demux



Ring filters



Polarisation splitters

Polarisation combiners



Polarisation independent  
differential delay lines



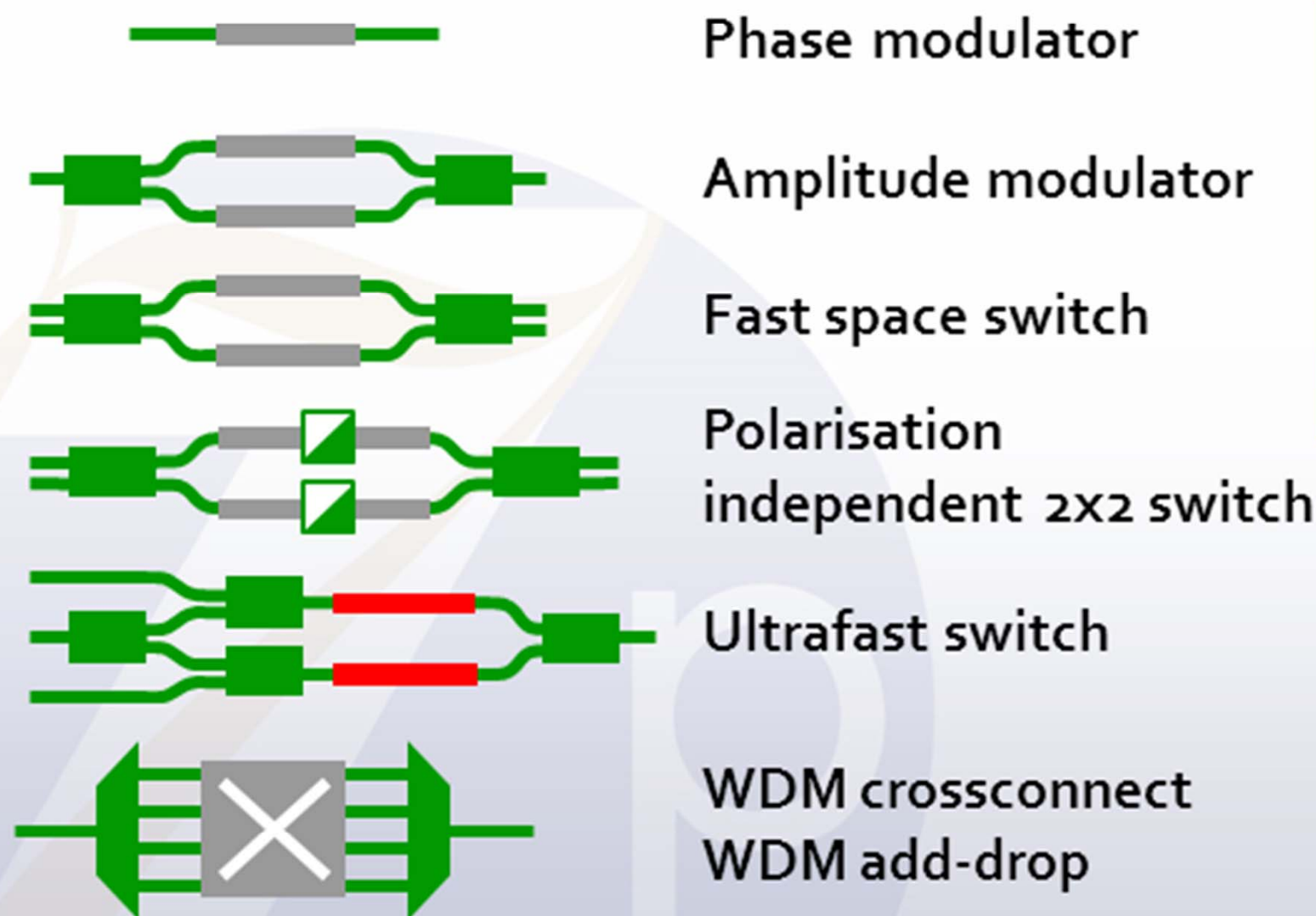
Thermo optic Phase modulator

Passive  
devices

InP  
Silicon  
TriPleX



# Generic technology: building blocks



**Switches  
Modulators**

**InP  
Silicon**



# Generic technology: building blocks



SOA



Fabry-perot lasers



Tunable DBR lasers



Multiwavelength lasers



Picosecond pulse laser



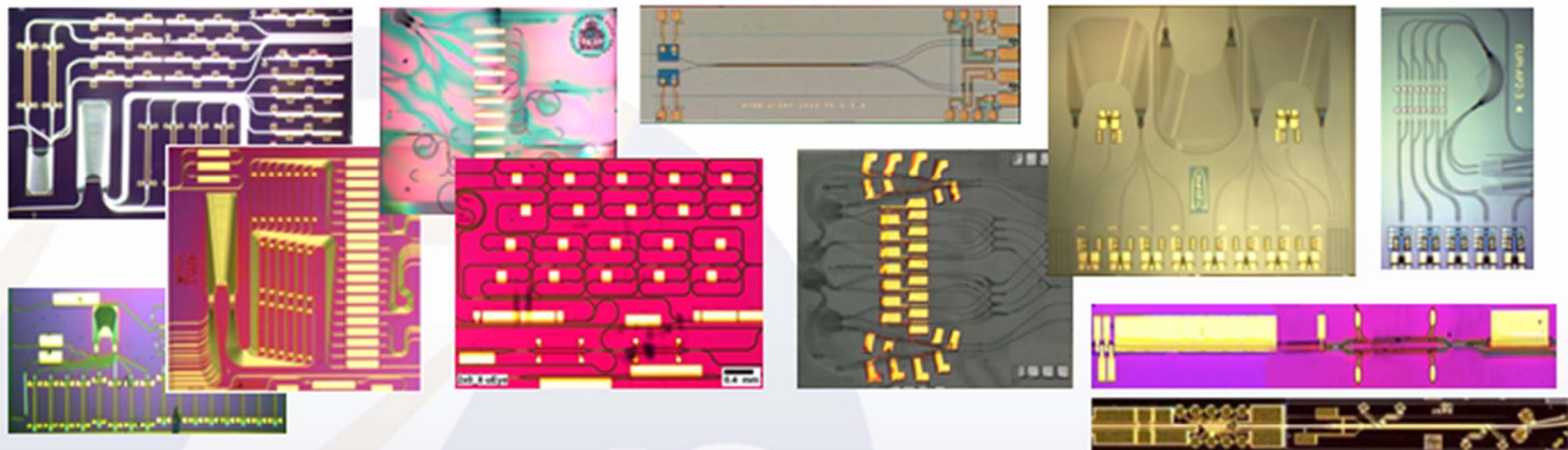
Ring lasers

Lasers

InP

# Generic foundry model

350+ ASPICs developed in generic fabs via MPW runs

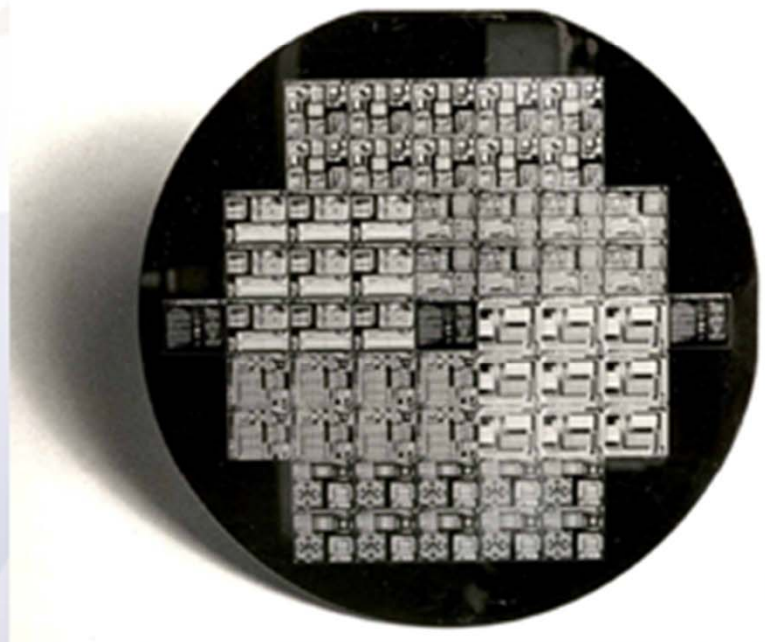


- Photonic advanced **PDK** with **BBs** available for **layout and simulation**, just like for electronics and CMOS designers
- Photonic **ASICs** fabricated using the **same processes**, using existing commercial manufacturing lines (towards volume production)

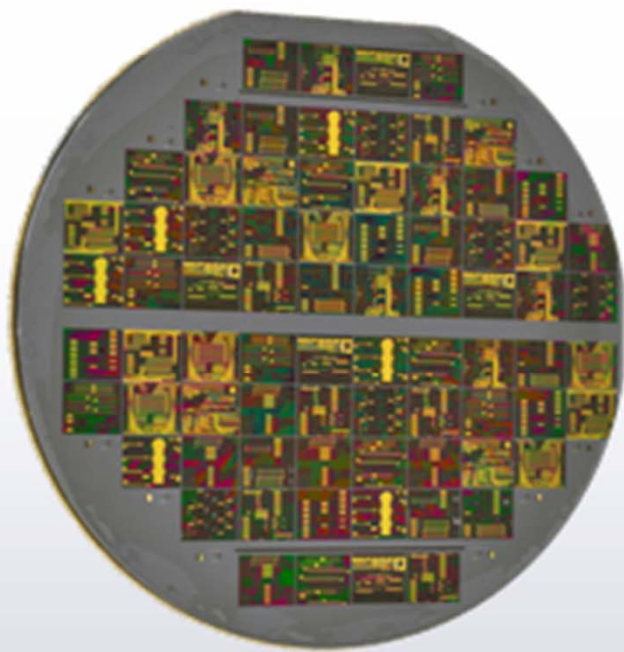


# Multi-project wafer runs

- Sharing wafer : sharing fab costs
  - simple and cheap way of prototyping
  - fabless business model



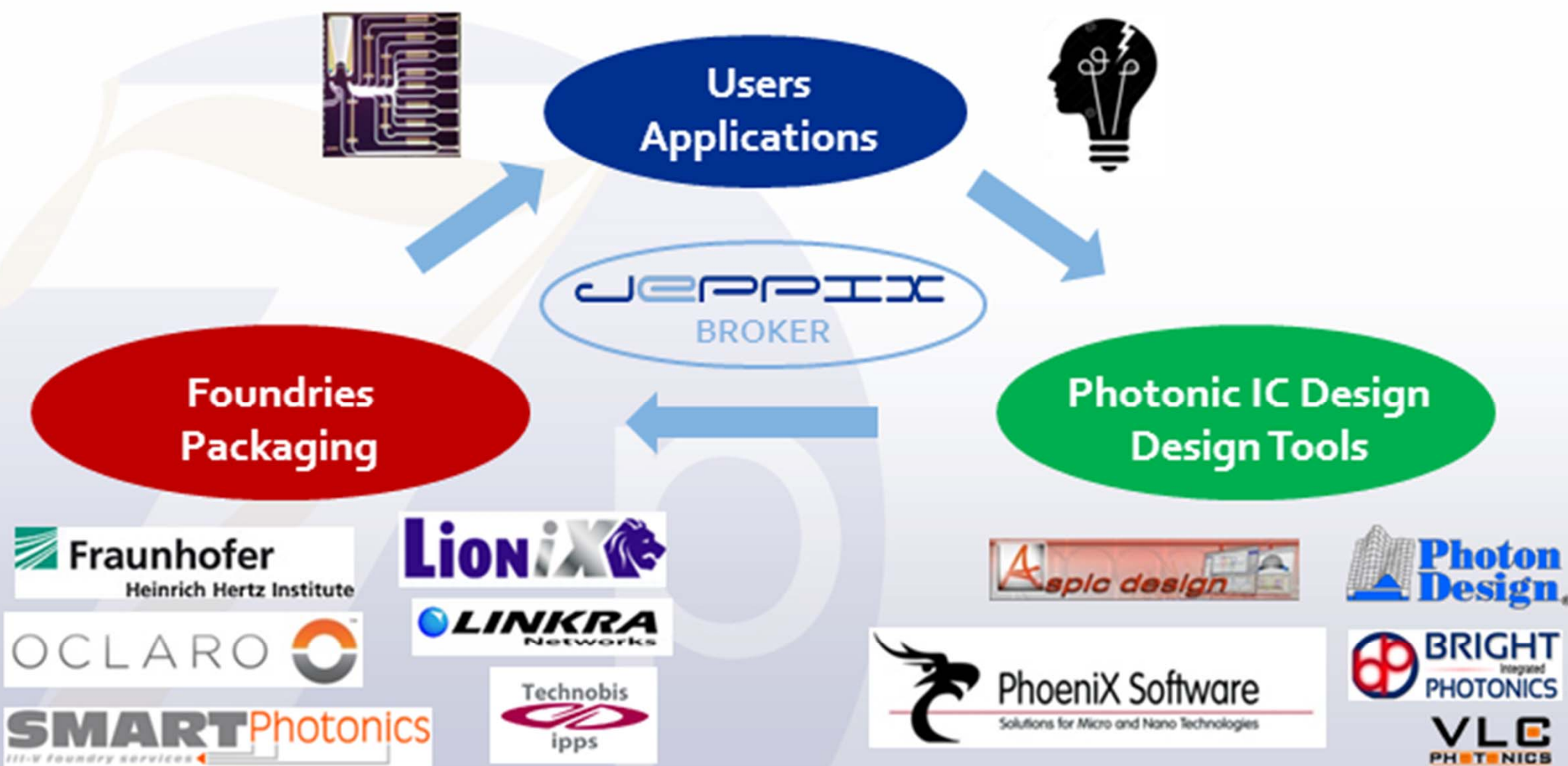
Silicon electronic ICs 1979  
**Electronic ICs**



InP photonic ICs today  
**vs. Photonic ICs**

# Broker: ecosystem for PIC development

✓ Design   ✓ Fabrication   ✓ Packaging



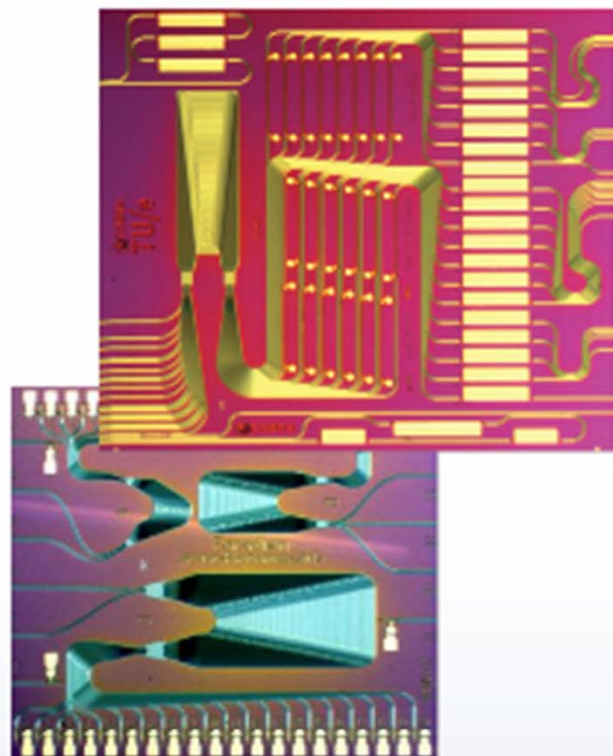


# Multi-project wafer runs in photonics

- Photonic ASIC prototypes in **InP MPW** fabs
- Active-passive on-chip integration

- ✓ Integrated lasers and amplifiers
- ✓ High speed detectors (40 GHz,  $I_{\text{dark}} < 100$  nA)
- ✓ High speed modulators (12.5 Gbps,  $V_{\pi} = 3.6$  V)
- ✓ Low-loss passives  $\leq 2.0$  dB/cm
- ✓ Tunable DBR gratings (up to 9 nm)
- ✓ Spotsizer converters

C-band wavelength range

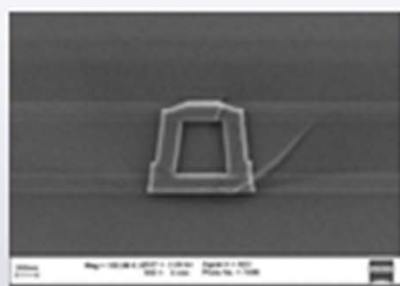
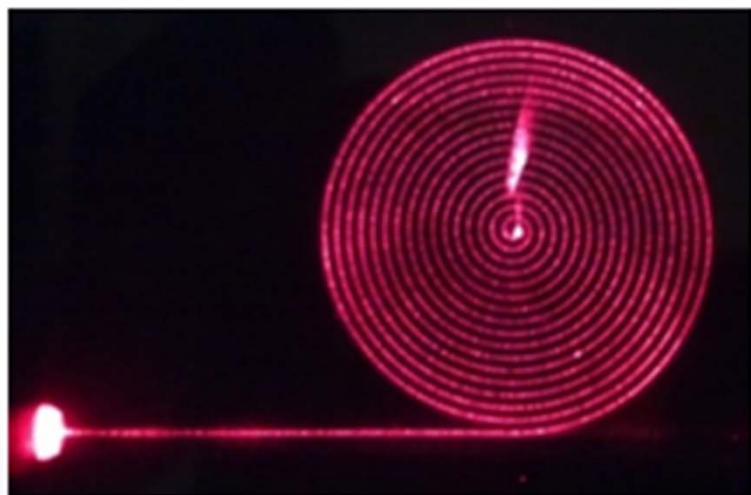


# Multi-project wafer runs in photonics

- Photonic ASIC prototypes in **TriPLeX MPW** fab
- Low-loss dielectric waveguides:
  - silicon nitride
  - silicon oxide

- ✓ High Quality Passives (AWG, MZ, ring, ..)
- ✓ Low-loss waveguides  $\leq 0.5$  dB/cm
- ✓ Bend radii 125  $\mu$ m allow real VLSI
- ✓ Thermo Optic Phase modulators

Visible light to IR transparency





# Multi-project wafer runs in photonics



## Standard Passives

Waveguide devices  
Grating Couplers

imec

cea **leti**



- Photonic ASIC prototypes in **Si MPW** fabs



## Advanced passives

Waveguide Devices  
High Efficiency Gratings

imec



## Heaters

TiN Heaters  
Thermo Optic Tuning

cea **leti**



## Microphotronics

Low loss waveguides  
Polarization insensitive

VTT

Passives

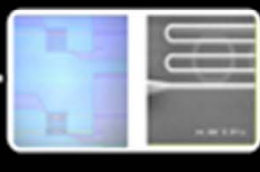
Heaters

Modulators

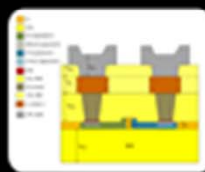
Detectors



+



+



+



• 4 etch levels in Silicon  
• High Efficiency Gratings

• Metal Heaters  
• Doped Heaters

• 10Gb/s Modulators  
• Faster Possible

• 10G detectors

imec

cea **leti**



PHI

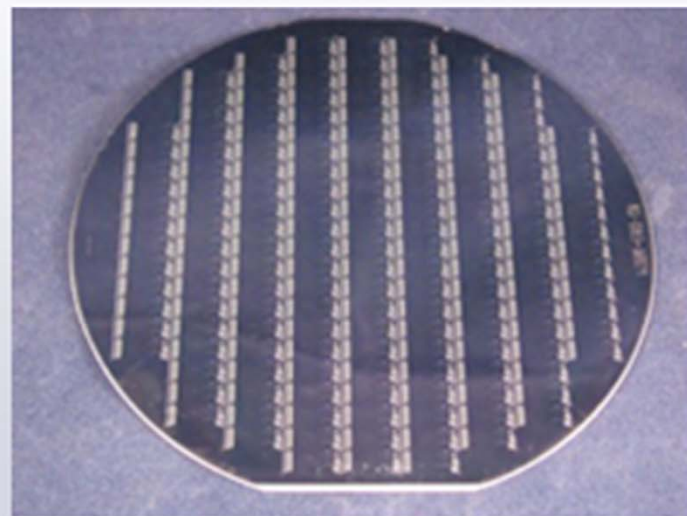
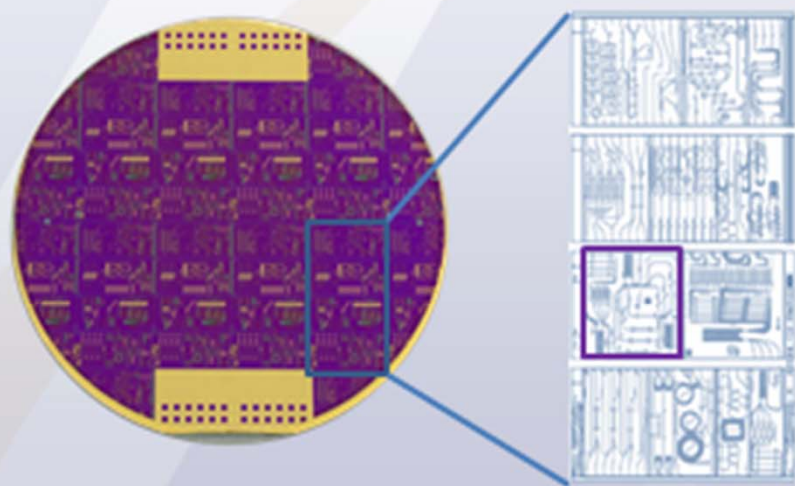
Phoenix Software

16-sep-14

p19

# Multi-project wafer runs in photonics

	InP	TriPleX	Si
Number of chips	5 – 10	4 – 10	10 – 50
Typical IC sizes	10 mm <sup>2</sup> to 36 mm <sup>2</sup>	25 mm <sup>2</sup> to 250 mm <sup>2</sup>	6 mm <sup>2</sup> to 100 mm <sup>2</sup>
Costs	€ 5000 to € 40000	€ 8500 to € 16000	€ 4000 to € 140000
Per mm <sup>2</sup>	€ 50 – € 150	€ 10 – € 50	€ 20 – € 170
Wafer size	2" – 3"	4"	6" – 8"
Chips per wafer	50 – 200	16 – 200	300 – 5000
	JePPIX	LioniX	ePIXfab





# Photonic Process Design Kits (PDKs)

16-Sep-2014



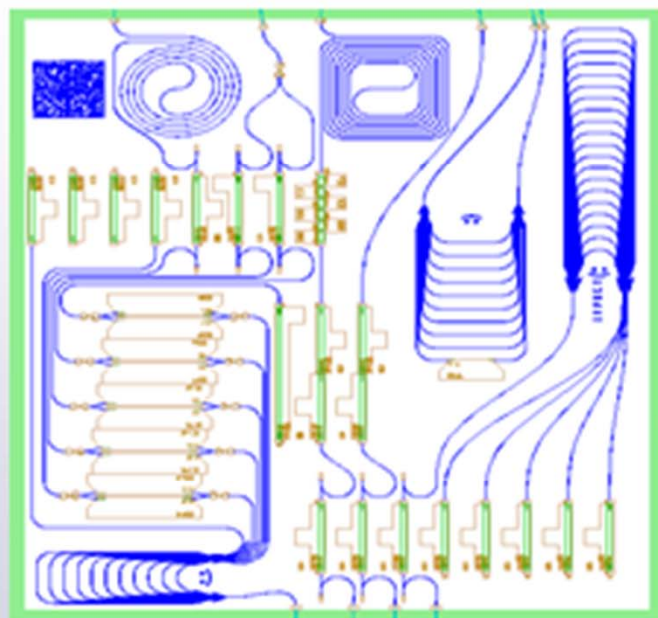
# Photonic design environment



- Efficient interaction between designer and fab requires
  - Ability to check designs for process variation / functional performance
  - Ability to use existing (photonics) building blocks
  - Ability to check the design for manufacturability
- This information is available in
  - Process Design Kits (PDKs)

# PDKs increase efficiency

- Chip development is unaffordable if many iterations are needed for a successful design
- Ability to check functionality and process design rules can make complex design successful at the first run
  - For a simple chip, smart designer can keep track and avoid mistakes.
  - For complex photonic chip, it is difficult to keep track of all the variable without automated design environment



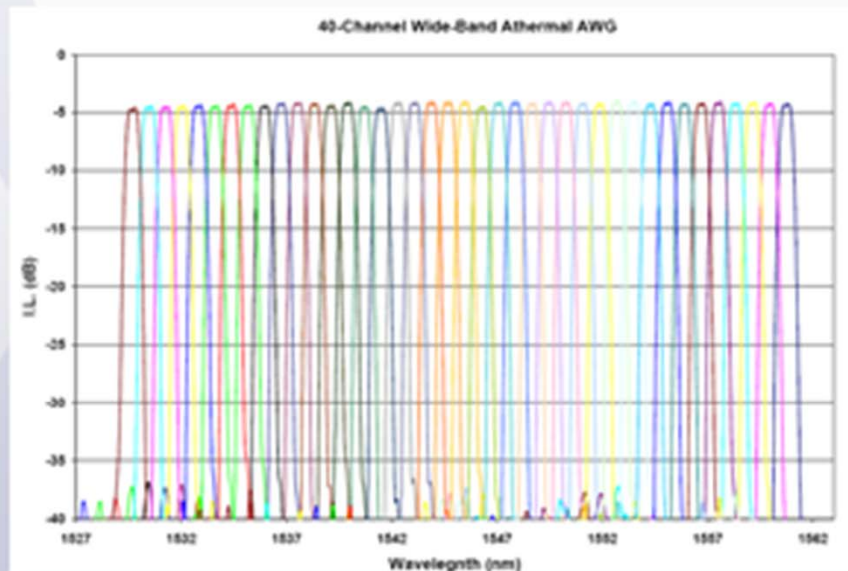


# Photonics $\neq$ CMOS

- Wafer volume  $\ll 1\%$  of CMOS
- Typical line width : 0.2 .. 3 micron
- Current process tolerances (too) high
- “RF-like” or “analog” behavior
  - Telecom C-band is 1530–1565nm =  $\sim 193$  THz

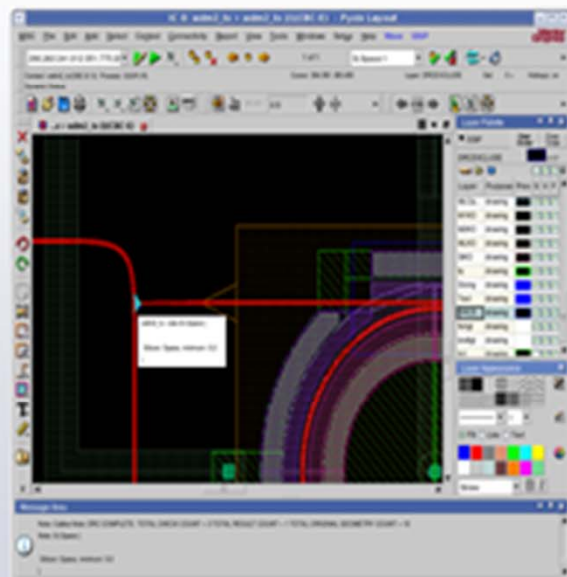
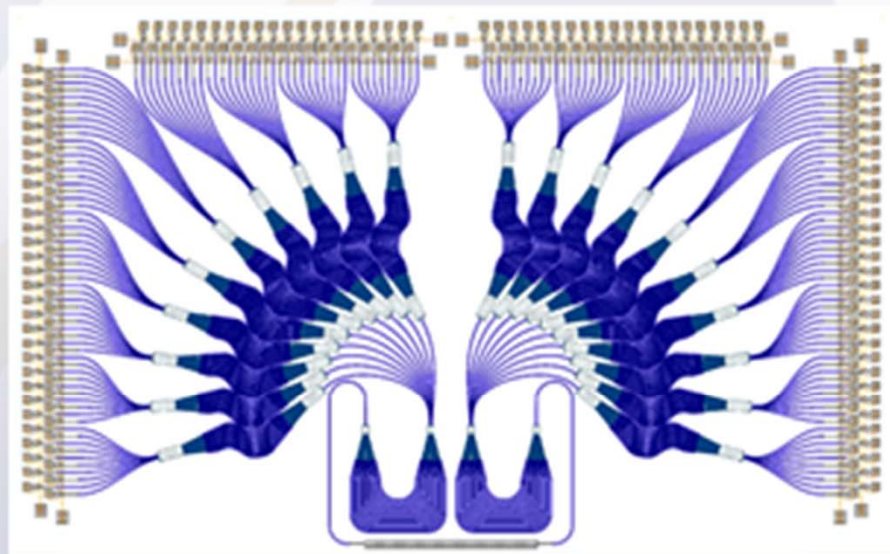


40 channel integrated optical multiplexer with a channel spacing of 100 GHz for telecom  
*Courtesy of Kaia Corporation.*



# Photonics $\neq$ CMOS

- “RF-like” or “analog” behavior requires:
  - Accurate and flexible definition of shapes (all angle)
  - Control of phase (differences)
  - Dedicated photonics simulation routines
  - Libraries with parametric photonics building blocks
  - Connectivity and “smart” routing routines



# Photonics $\neq$ CMOS

- Fabs are using Electronics Design Automation (EDA) tools, especially for Design Rule Check (DRC), sign-off and tape-out
- Photonics designers are using Photonics Design Automation (PDA) tools
- EDA tools are *not all* suitable  
All angle designs, shape definition, simulations, DRC
- PDA tools require *additional* capabilities  
Mature DRC, auto-routing, LVS, ORC, RET

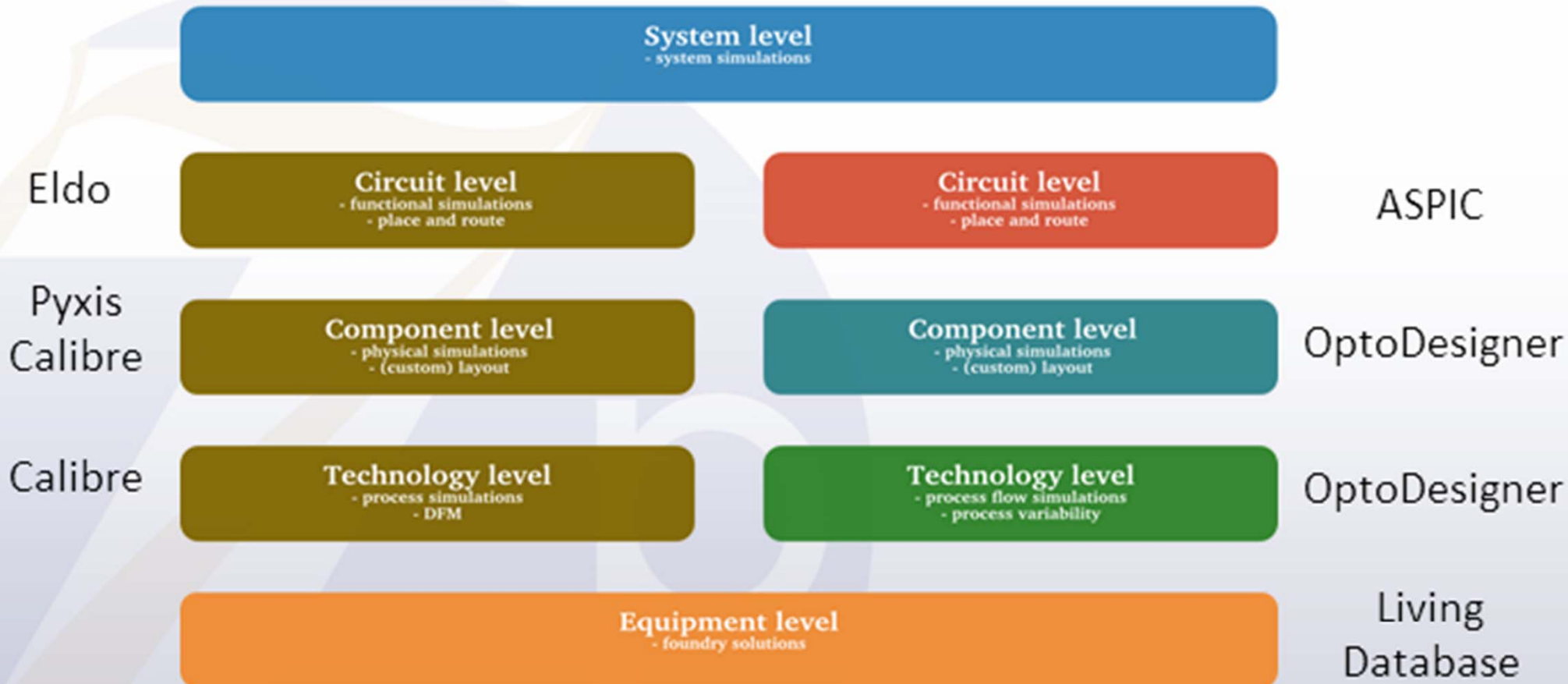


# PDA & EDA design flows



EDA flow

PDA flow



# PDKs can always be used

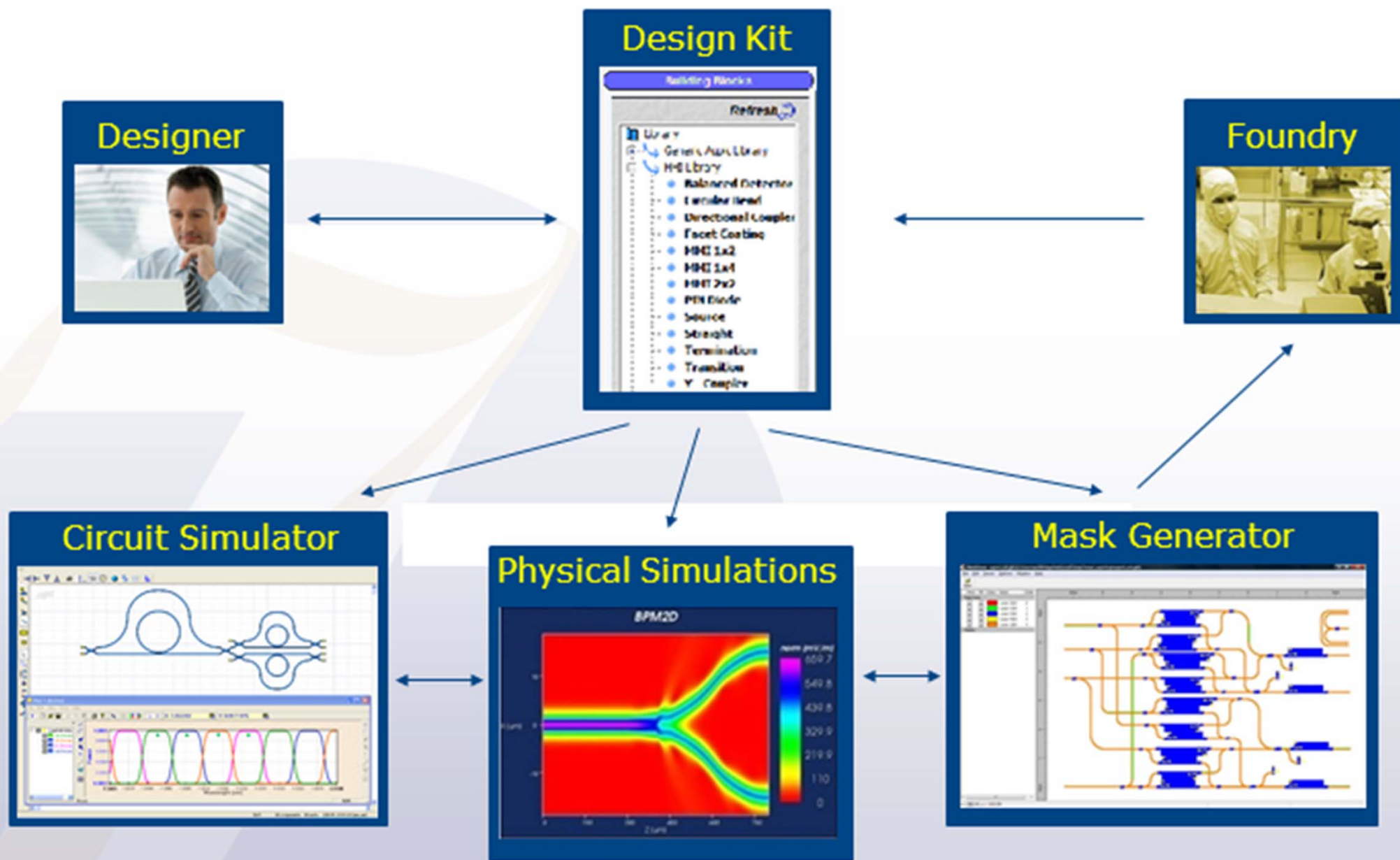
- PDKs can be used internally or when working with an external fab or foundry
- PDKs are provided as a plug-in library for the software environment
- Software vendors are working together to further improve and standardize

- SP-TAB 

- PDAFlow Foundation



# Using a PDK in PDA style design flow





# PDA style photonics design flow

*Parametric Photonics  
Building Block*

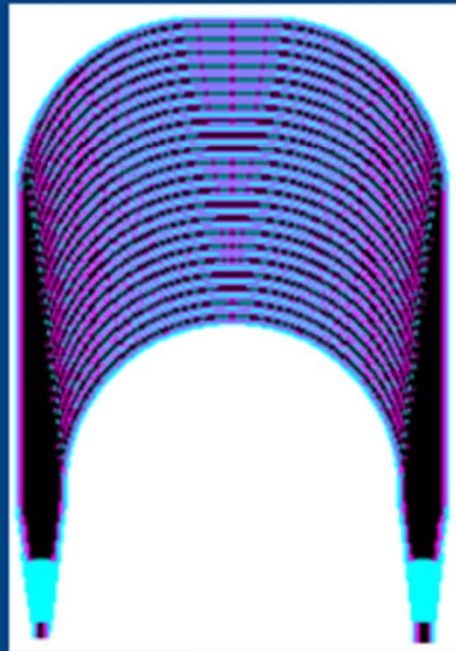
**AWG Building Block**

*plus PDK...*

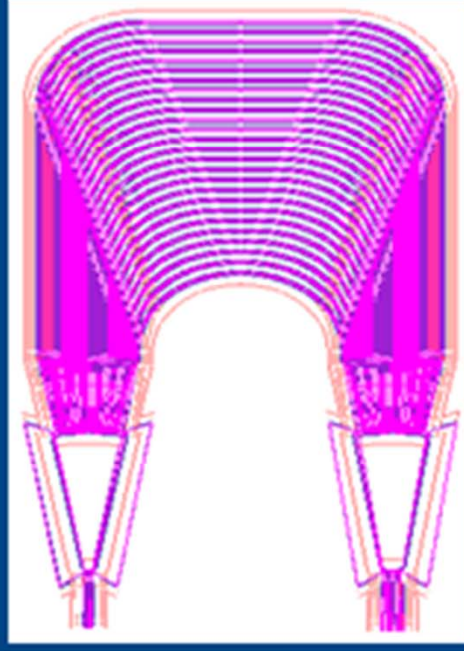
*quickly ports  
to multiple  
foundries*



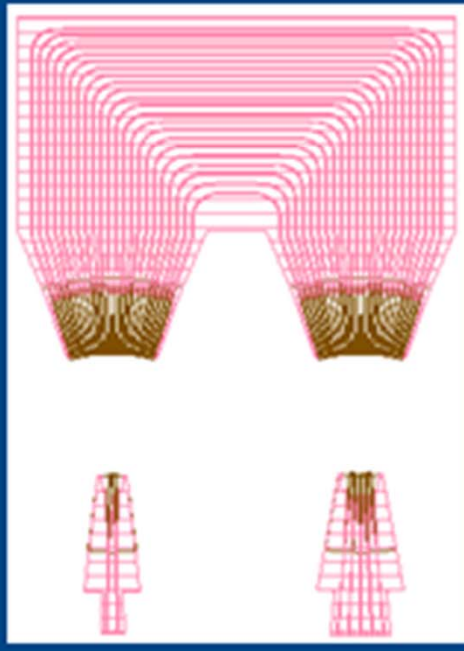
**HHI/FhG MPW  
(InP)**



**TU/e-COBRA MPW  
(InP)**

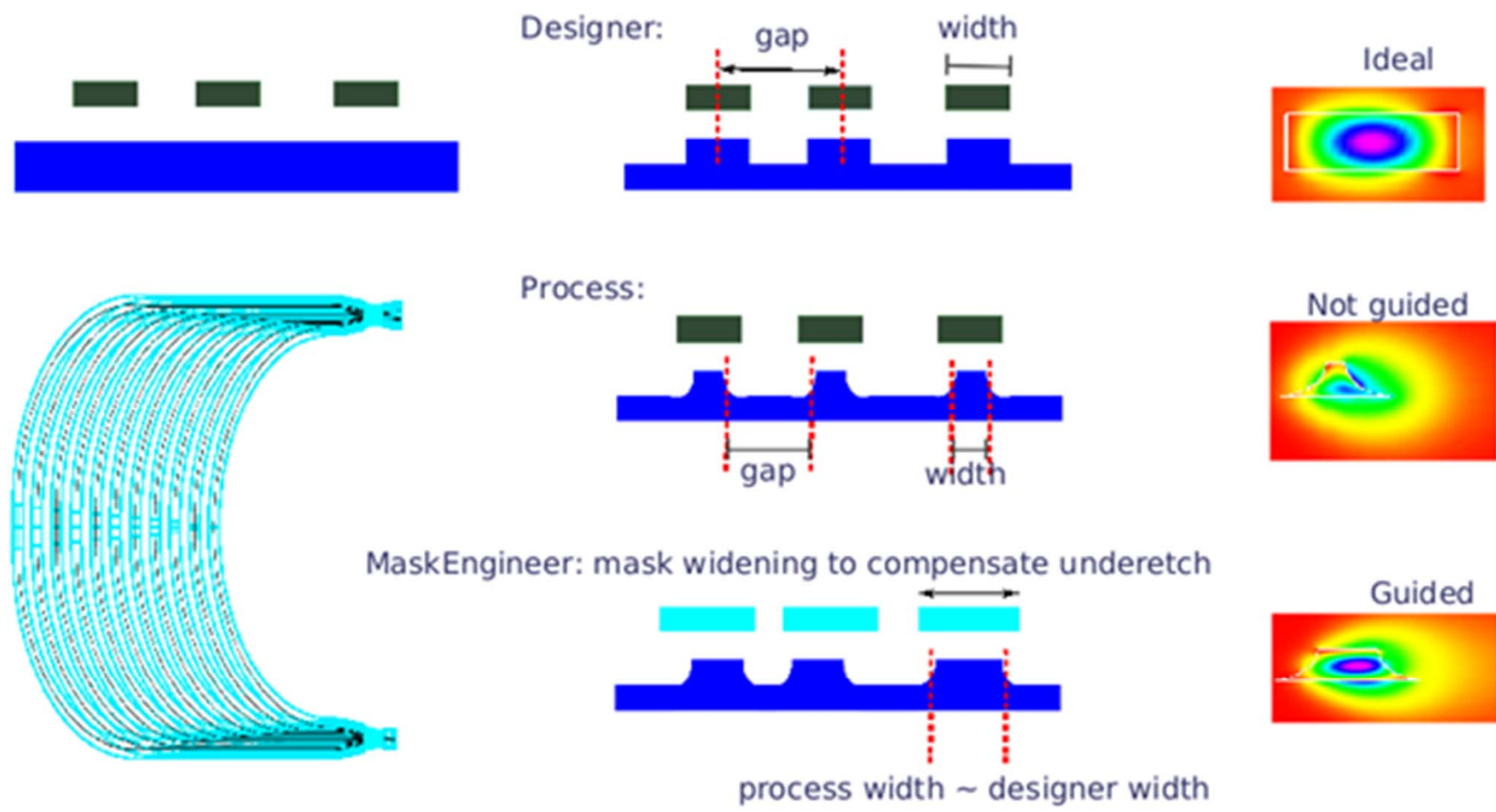


**IMEC MPW  
(SOI)**



# PDA-style photonics design flow

- Phoenix Software OptoDesigner 5 Photonics Design Suite integrates photonics simulations, process information and layout.



# PDA style photonics design flow

- Physical and functional verification



- Functional verification with OptoDesigner 5 flags that bend R is too small in original design
- When correcting for this, in/outputs need to be elastic
- Full physical DRC at GDS level with Mentor Graphics Calibre
- PhoeniX Software and Mentor Graphics working on improvements in the flow from OptoDesigner 5 → Calibre

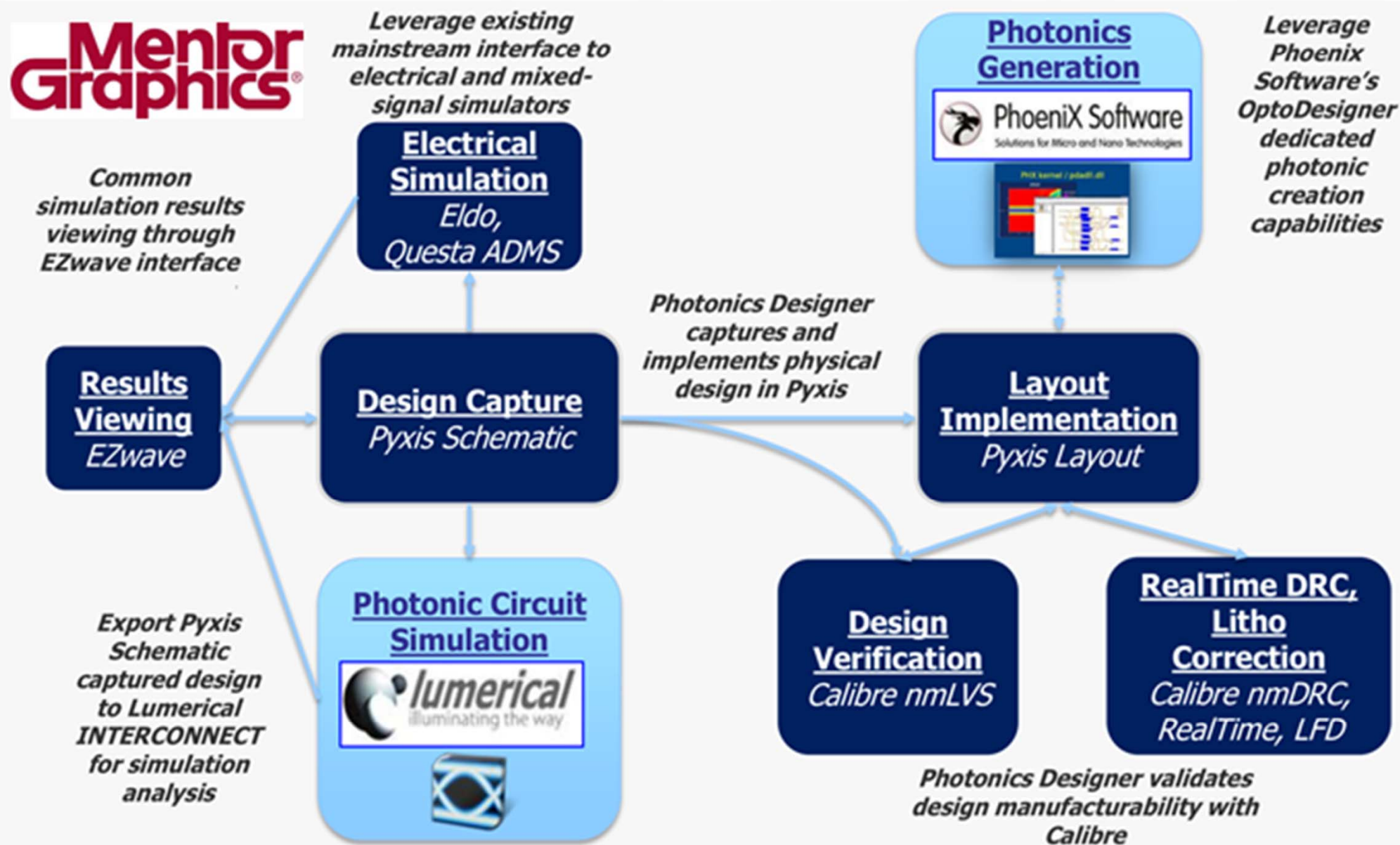


# EDA style custom design methodology

*What role does the EDA style custom methodology play in Silicon Photonics?*

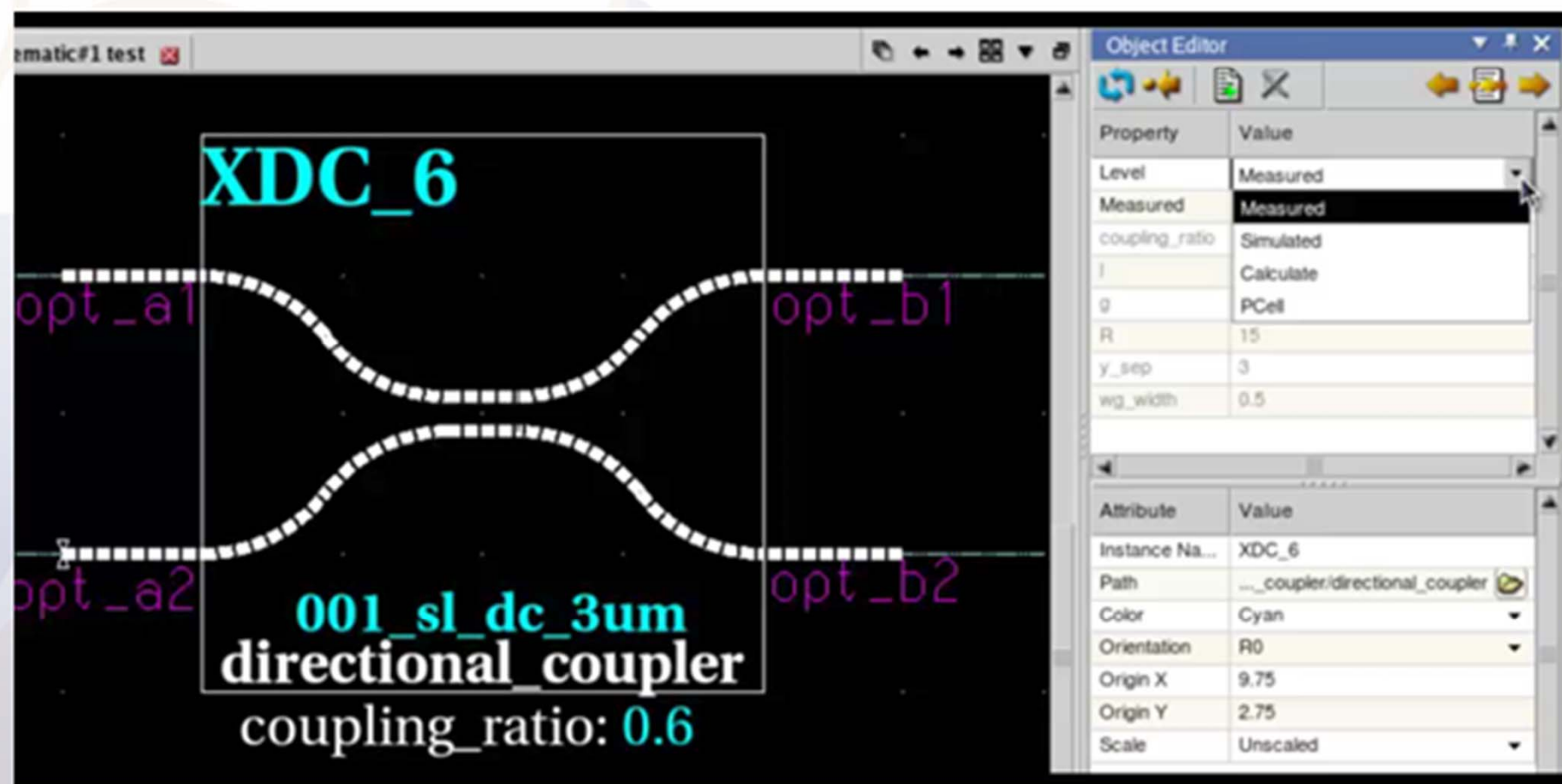
- EDA methodology has a Proven track record for:
  - Large scale custom integration of components (building blocks)
  - Multi-user / multi-site design
  - Flexible 3rd party tool and data integration
  - Existing integration to physical verification tools

# EDA style photonics design flow



# EDA style photonics design flow

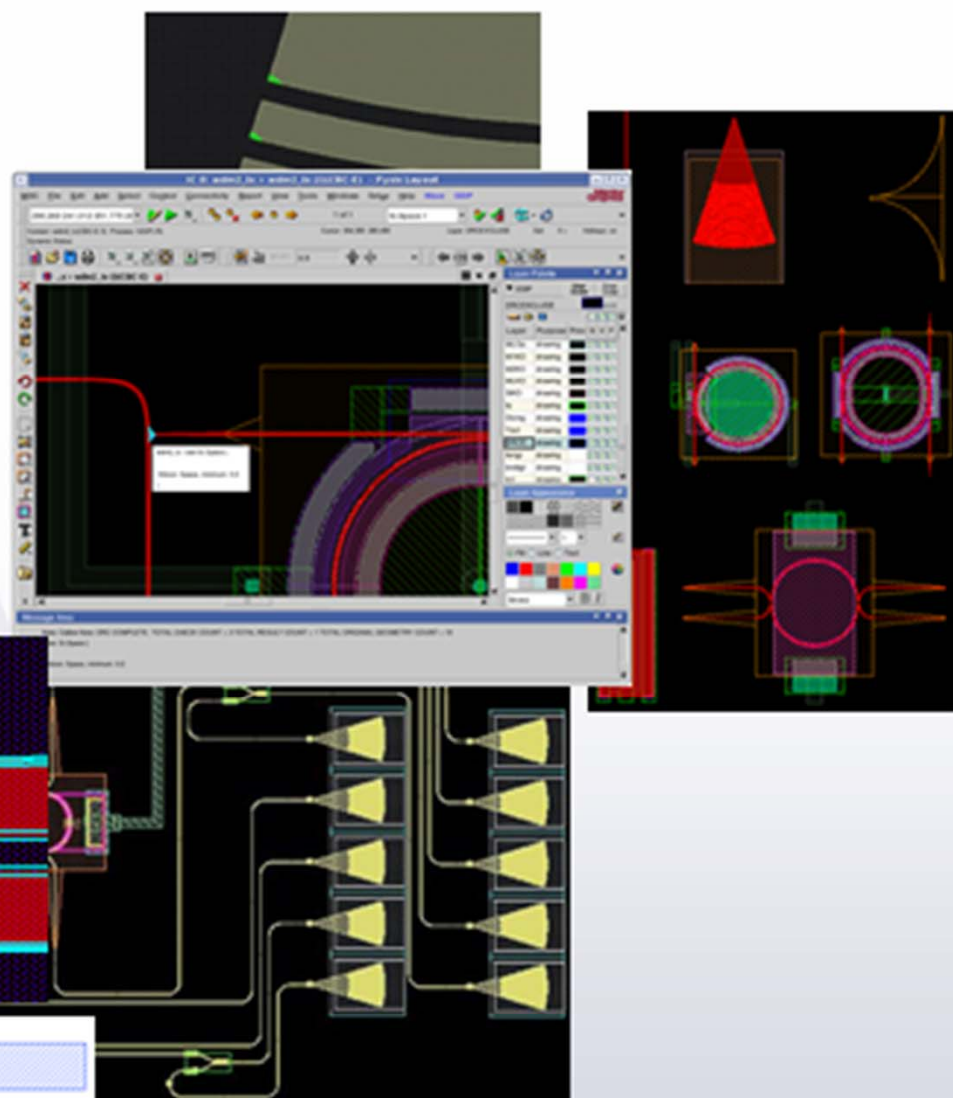
- Enabling Design Intent Based Functionality
- Accelerating innovation by allowing users to configure components in terms of system parameters, not geometries





# Physical verification for Silicon photonics

- Calibre Verification Platform
  - Reducing “False” DRC Errors
  - RealTime design integration
  - Recognize & extract photonic devices
  - Open detection & short isolation
  - Wave guide curvature verification
  - Lithographic Simulation

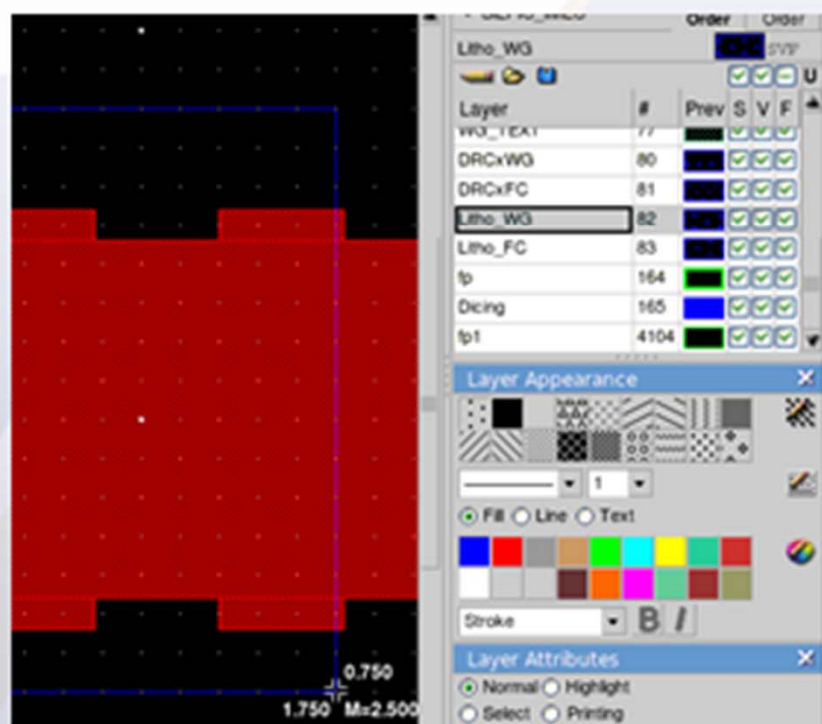


Drawn

Litho-simulated

# Physical verification for Silicon photonics

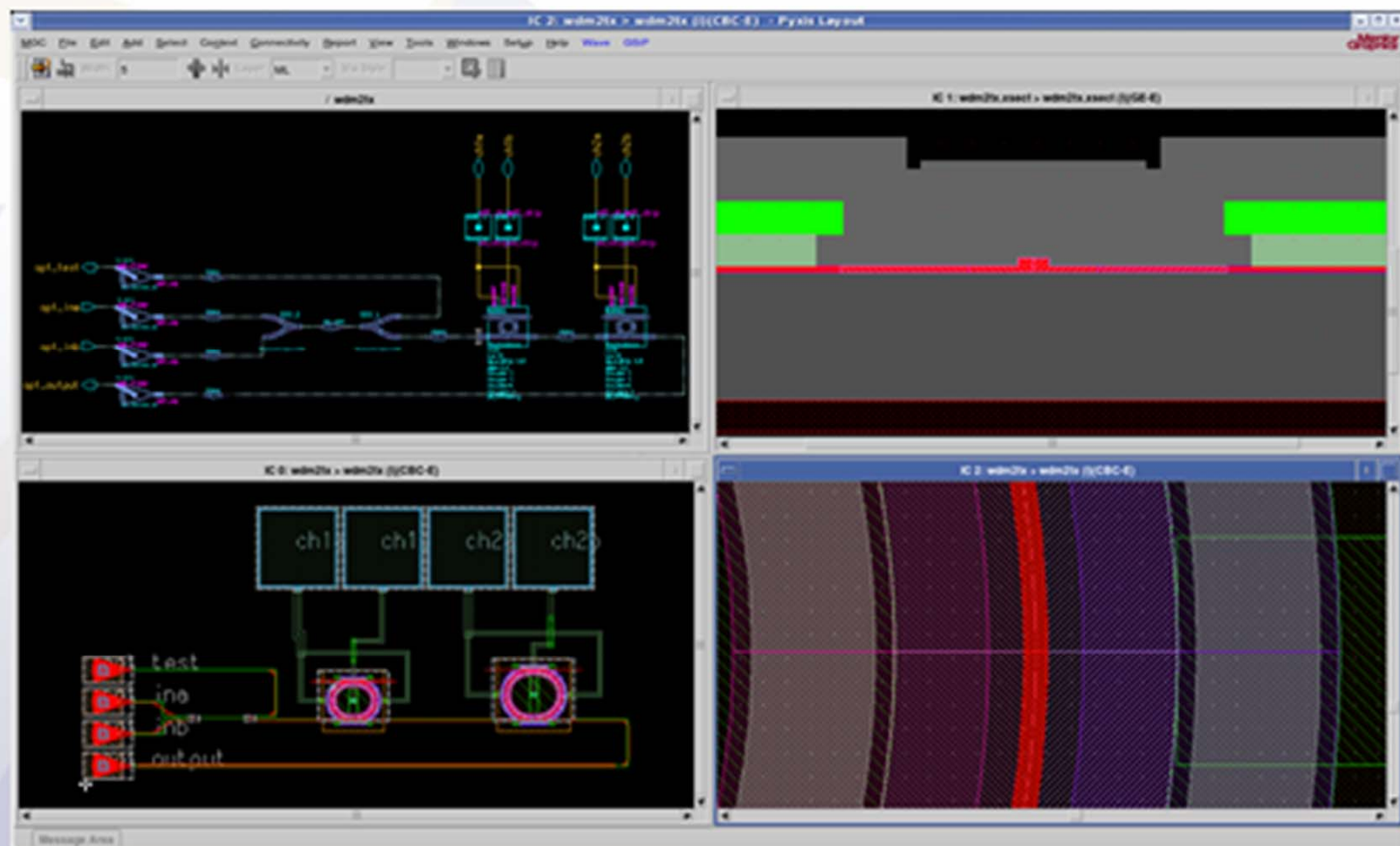
- LFD Example: Waveguide Bragg Grating
  - Ideal sharp edges of grating will smooth due to lithography resolution
  - This change in geometry will affect component attributes
  - Run a Calibre LFD lithography simulation directly in Pyxis Layout window with Calibre RealTime or on exported GDS/Oasis data





# EDA style photonics design flow

- Reference GSiP Package
  - Mentor working with Si-EPIC program and the University of British Columbia to create a NDA neutral Si Photonics PDK
  - Demonstrates full silicon photonics design flow





# PDKs compatible with Phoenix Software

- Silicon: IMEC, CEA-Leti, VTT, IHP and OpSIS-IME
- InP: FhG/HHI, Oclaro, SMART Photonics and TU/e-COBRA
- TriPleX (SiO<sub>2</sub>/Si<sub>3</sub>N<sub>4</sub>): LioniX
- Packaging: Linkra, XiO Photonics, Tyndall, Technobis ippis and Chiral
- PDKs are typically made available through MPW service organizations
- More than 250 designs taped-out with PDKs and Phoenix Software's design tools in the last two years



# PDKs for Mentor Graphics

- IME and IMEC Foundry PDKs (Available through CMC/Si-EPIC)
  - “designed to train undergraduate and graduate students and postdoctoral fellows across Canada in the new discipline of ... (ICT) systems that involves miniaturization of optical components onto silicon chips”  
<http://siepic.ubc.ca>



Si-EPIC

- IMEC (PDK in development)
  - Basic PDK available – working on full flow functionality

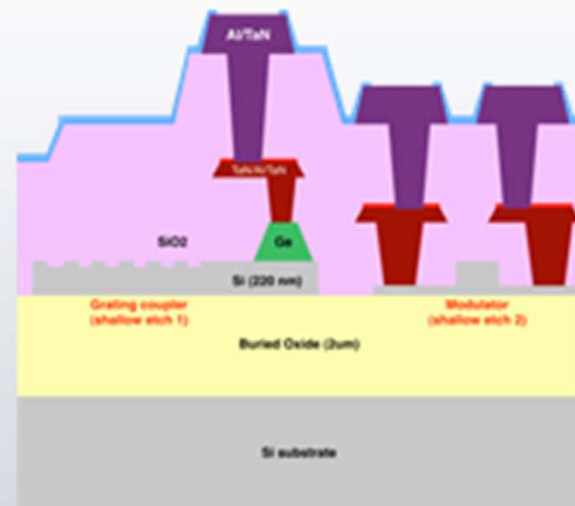


- OpSIS (Using IME)  
no longer available as of May 2014
  - <http://opsisfoundry.org>



## IME

- Passives
- Modulators
- Detectors
- Edge / grating coupling



# Material Systems

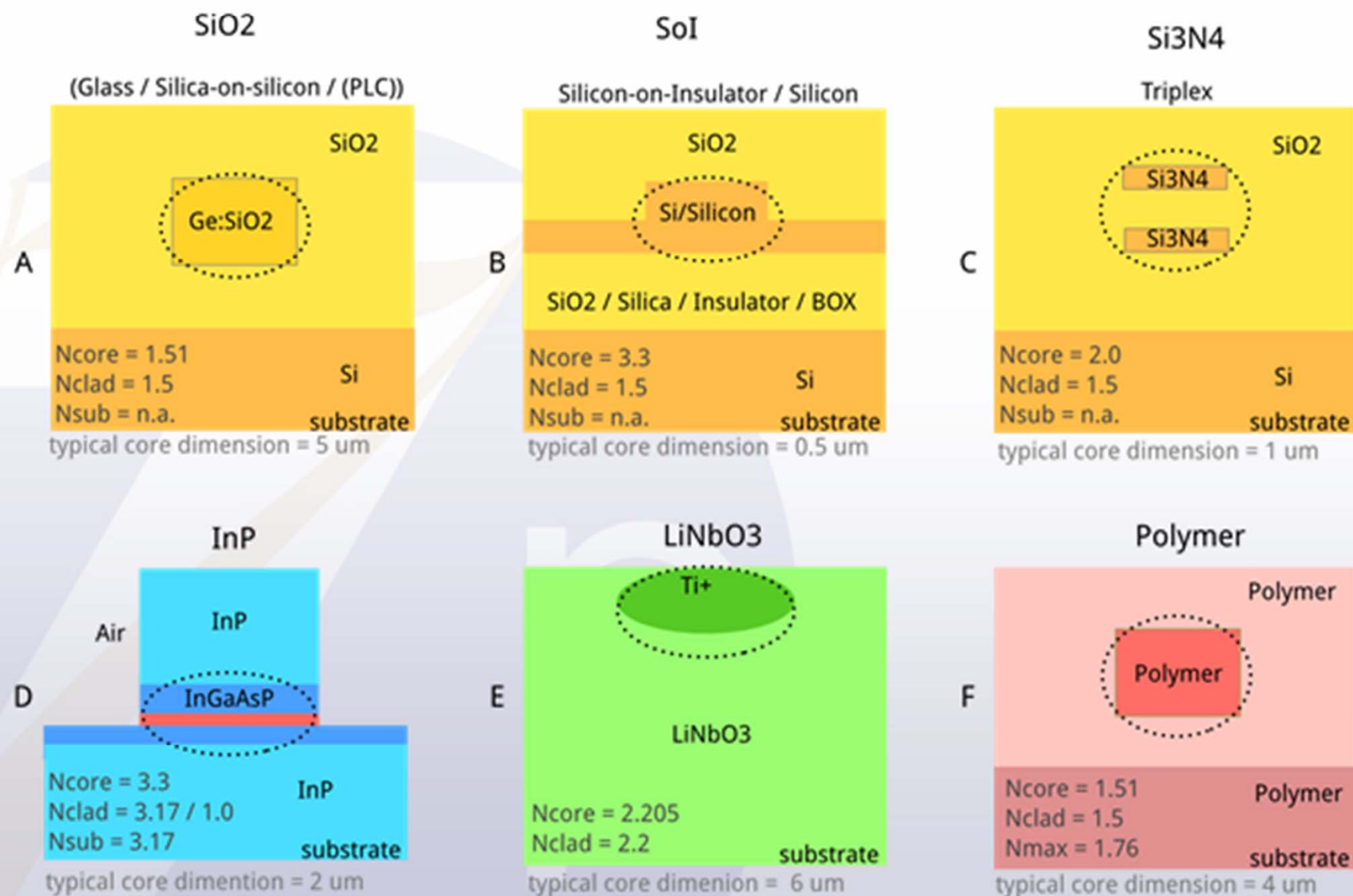
16-Sep-2014





# Material systems for integrated optics

## Cross sectional view of the waveguides



# Material systems: a comparison

A high-level functionality overview

property	Material system					
	A InP	B Sol	C Si3N4	D SiO2	E LiNbO3	F Polymer
1 Loss	good	good	good	good	good	good
2 Optical amplification	good	challenging/no	challenging/no	challenging/no	challenging/no	challenging/no
3 Photodiodes	good	good	challenging/no	challenging/no	challenging/no	challenging/no
4 Fiber coupling	good	good	good	good	good	good
5 Spectral range	good	good	good	good	good	good
6 Polarization indep.	good	challenging/no	good	good	challenging/no	good
7 RF modulation	good	good	challenging/no	challenging/no	good	good
8 CMOS compatible	challenging/no	good	good	good	challenging/no	challenging/no
9 Durability	good	good	good	good	good	challenging/no
10 Footprint	good	good	good	medium	medium	medium
11 All-in-one	good	good	good	challenging/no	challenging/no	challenging/no
12 MPW	good	good	good	challenging/no	challenging/no	challenging/no

good  
medium  
challenging/no

RF: Tx, Rx  
All-in-one

True-time delay  
Microwave photonics

Telecom Tx  
low voltage RF modulators

Data centers  
4x25 Gbit  
High volume

High quality passives  
Demux. splitters

Modulators  
Cheap hybrid

# Material system: more than just material

- What is best for the final application?
- Material and more:
  - Technical merits
  - Specific foundry
  - Reproducibility
  - Post processing
  - PDK available
  - Cycle time
  - Design support
  - Packaging options
  - Cost of prototype
  - Ramp-up
  - Cost of end product



# From application to material

Application → Functional BB → Technological BB → Material

## A. Passives



couplers



true-time delay



AWG-demux



ring filters

## B. Phase control



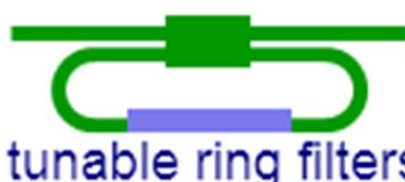
phase modulator



amplitude modulator



WDM add-drop



tunable ring filters

## C. Amplification



gain or non-linear mixing



tunable DBR lasers



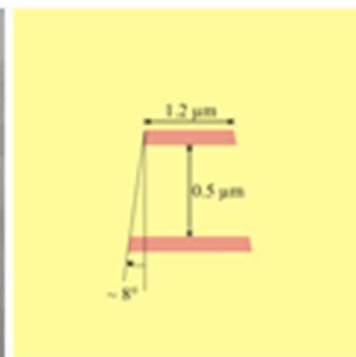
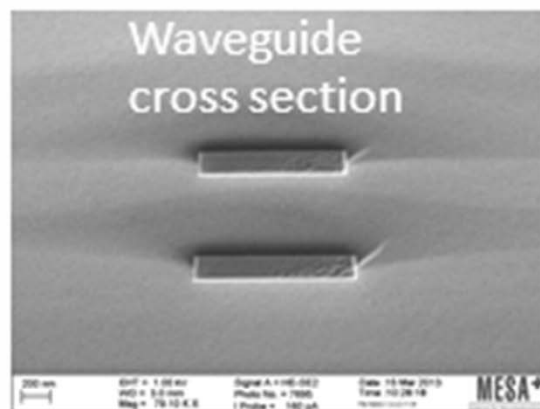
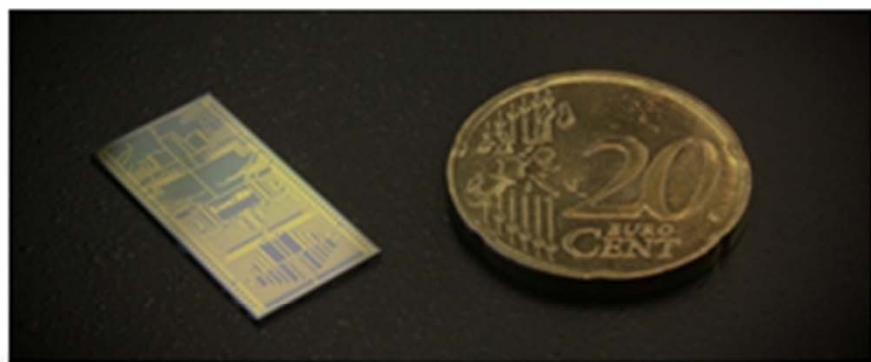
multiwavelength lasers



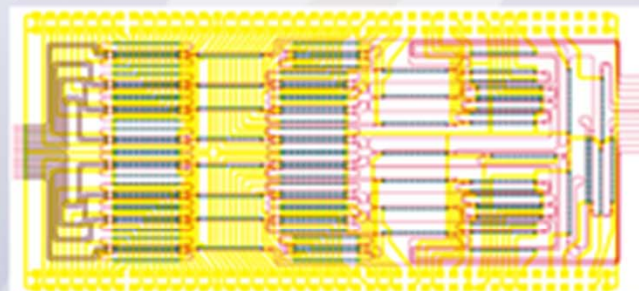
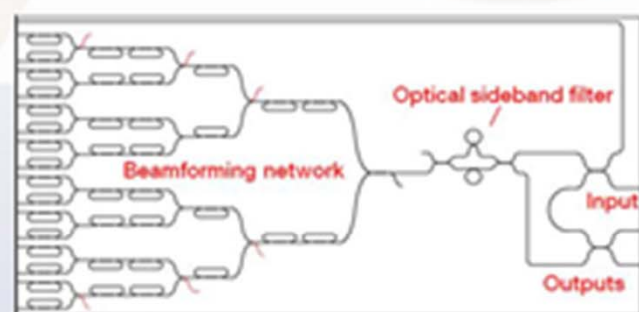
picosecond pulse laser

# TriPleX™ technology ( $\text{Si}_3\text{N}_4$ )

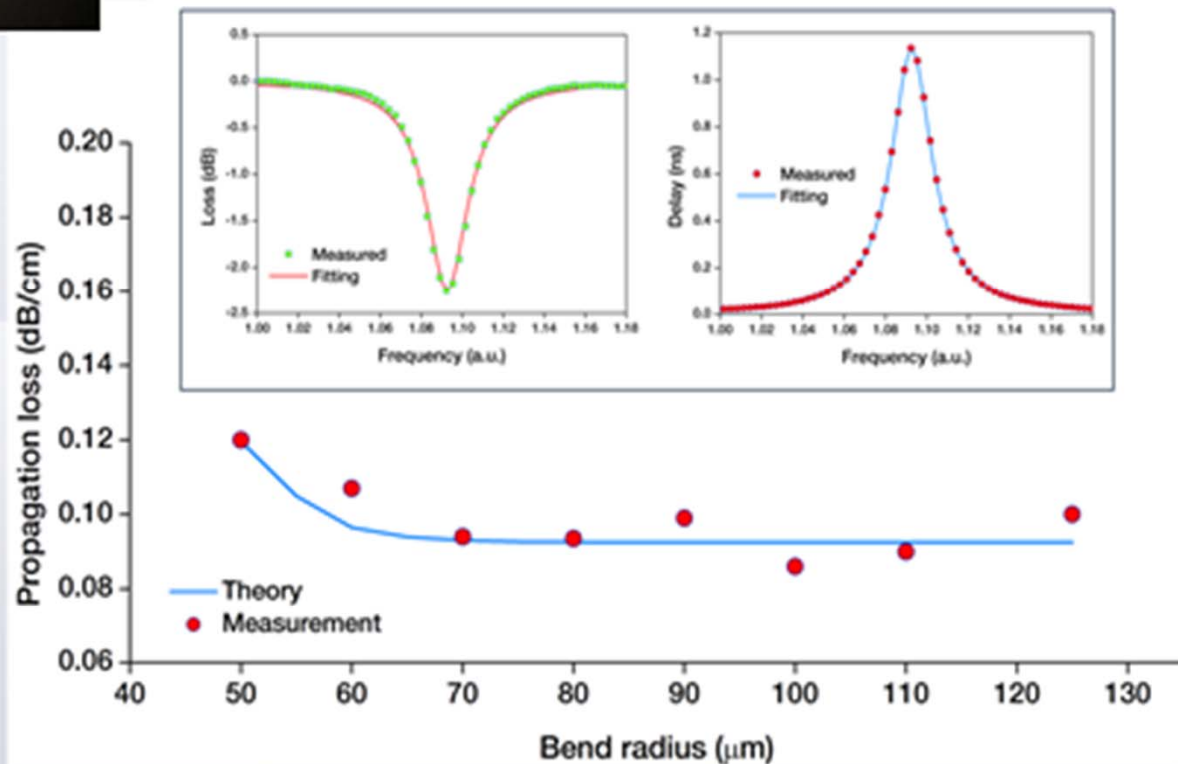
high contrast & low loss for time delays



■ Silicon oxide  
■ Silicon nitride 170 nm thick

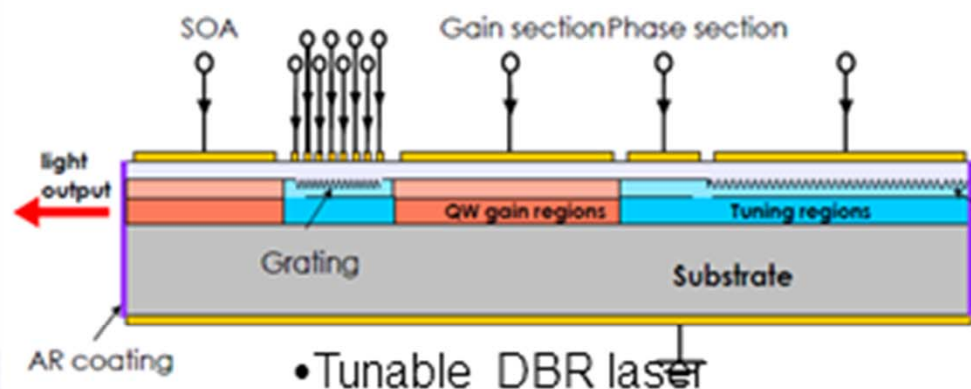
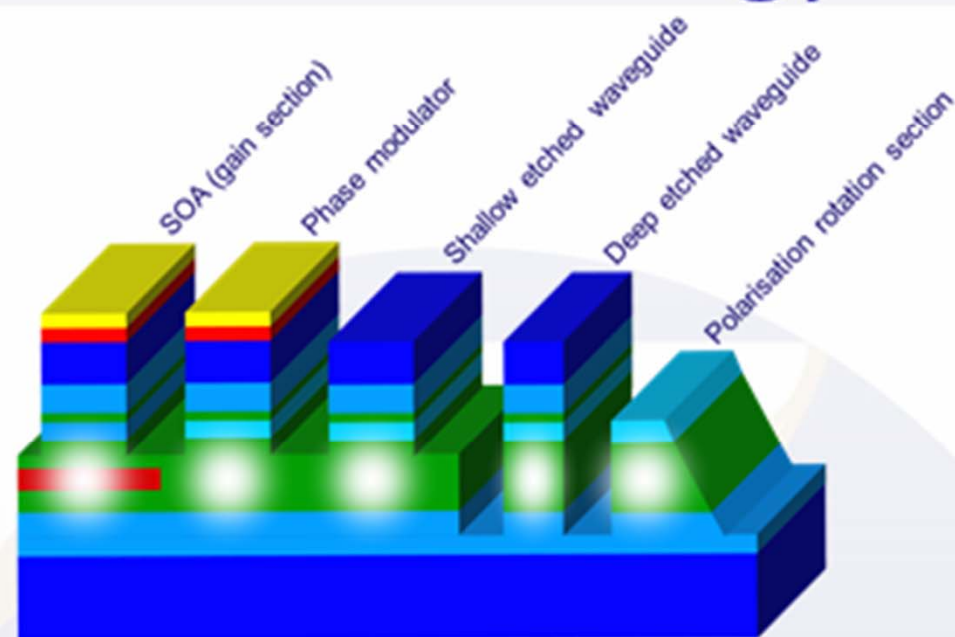


L. Zhuang, L. et al.  
Optics express, 19 (23), pp. 23162-23170

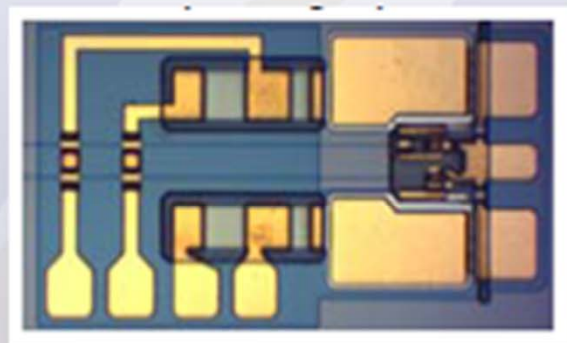
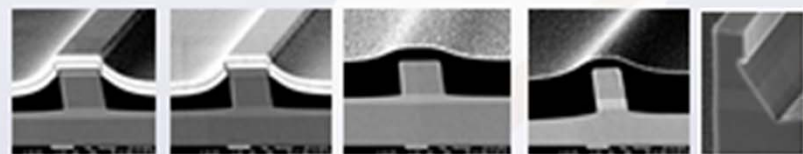


Propagation loss 0.1 dB/cm

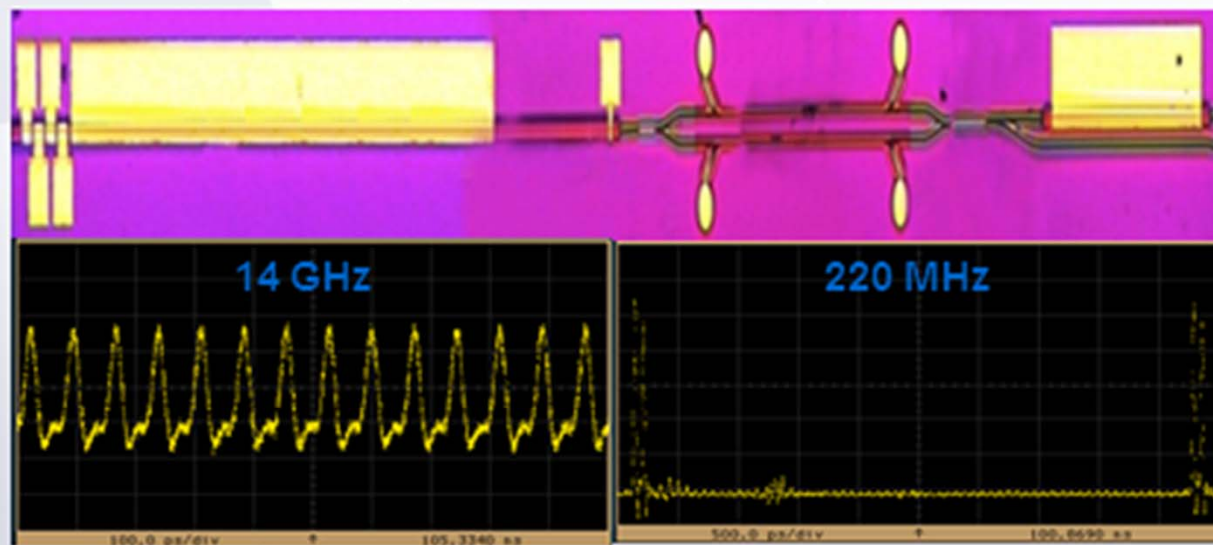
# InP technology: versatile with laser



Variable rep-rate laser for bio-photonics



• 40GHz pin-PD



X Guo et al, ISLC, San Diego, 2012



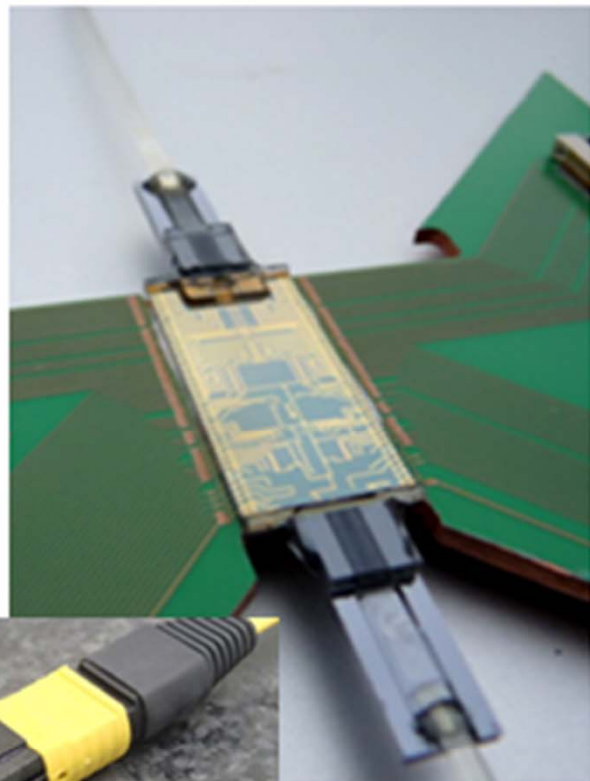
# Packaging, Scaling to Full Production and Intellectual Property

16-Sep-2014



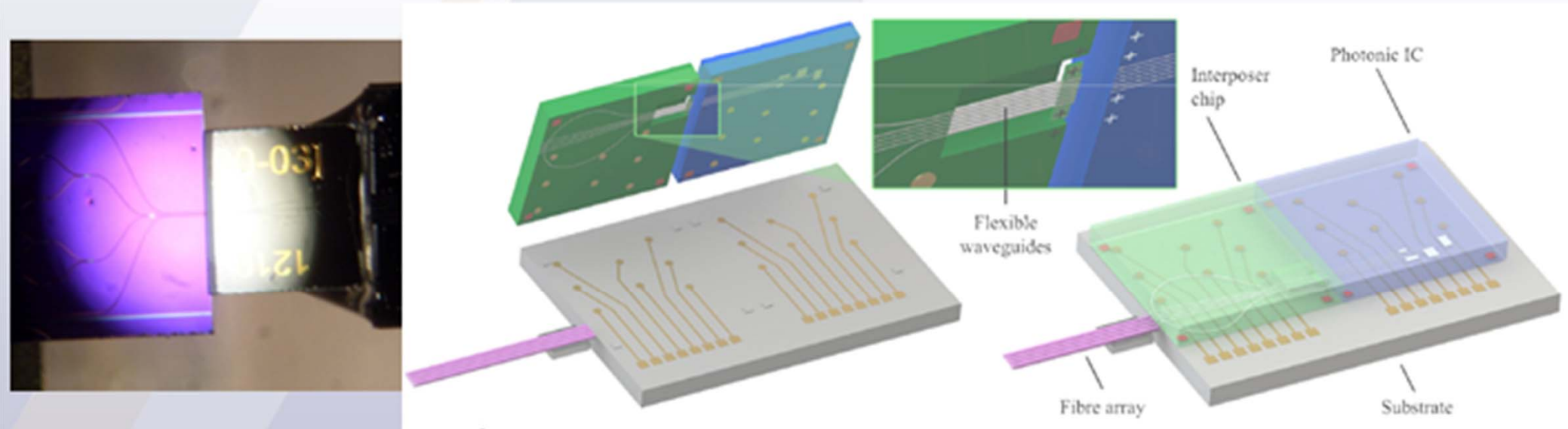
# Packaging and Hybrid integration

- Lot of MPW users come from R&D => Not used to measuring on bare dies.
- Both optical and electrical (RF) connections
- Design rules for packaging implemented in the design kits
- MPW foundries offer prototype packaging also
  - JePPIX => Linkra + G&H
  - ePIXfab => Tyndall
  - LioniX => XiO Photonics
- For volume production dedicated packaging foundries available in the world. Optocap, Aifotec, ....



# Packaging and Hybrid integration

- Heterogeneous integration not easy accessible
- Chips for hybrid integration easy accessible via MPWs
- New applications will emerge based on hybrid combinations of platforms. Use the best of all worlds.
- E.g. Create active functionality in low loss TriPleX platform => New FP7 initiative PHASTFlex (<http://www.phastflex.eu>)



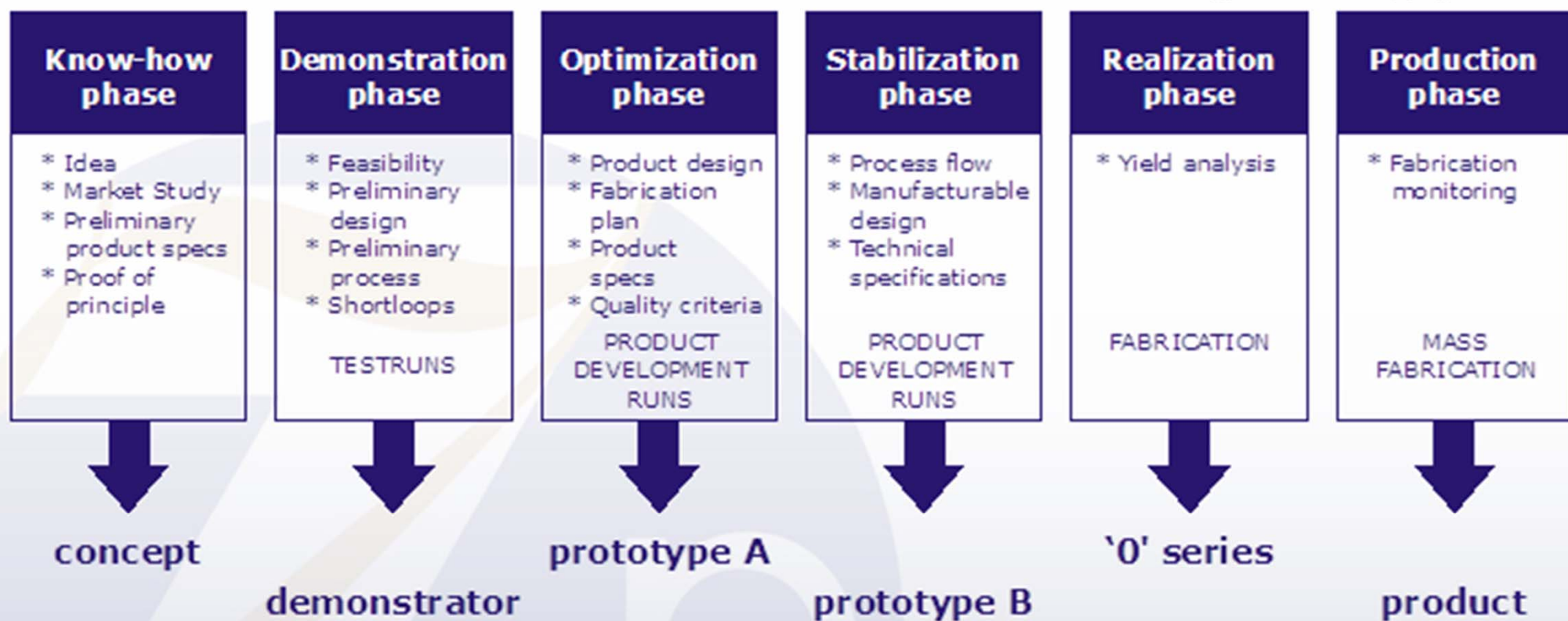


# Scaling production beyond prototypes

- Initial development only requires a limited number of chips => MPW suitable for low cost and high reproducibility
- For higher volume production dedicated engineering or production runs more suitable.
- Developing in stable MPW platform prevents additional iteration when scaling up.
- Road to volume production assured by using MPW platform

# Scaling production beyond prototypes

LioniX BV Strategy scheme © copyright 2002



- Prototype phases require less iterations if a stable MPW platform can be used => Designing first time right

# Dealing with intellectual property

- Process validation is not done on specific device performance:  
⇒ building block validation only
- Processes are typically owned by the foundry
- Chip design/layout is typically owned by the customer
- Specific Foundry design IP is shielded in confidential private building blocks (owned by the foundry)
- IP rules are similar to Electronics industry





# Private building blocks

- The MPW participant sees a mockup (pink) within a bounding box with the name of the private building block (brown), together with his own design (red) in the viewer of OptoDesigner



- DRC checks are carried out, files for the foundry are generated, amongst which a mask file (gds), that contains a hole at the position of the private building block



- After transferring the files to the foundry, the software inserts the private mask layout of the foundry (not shared with the participant)



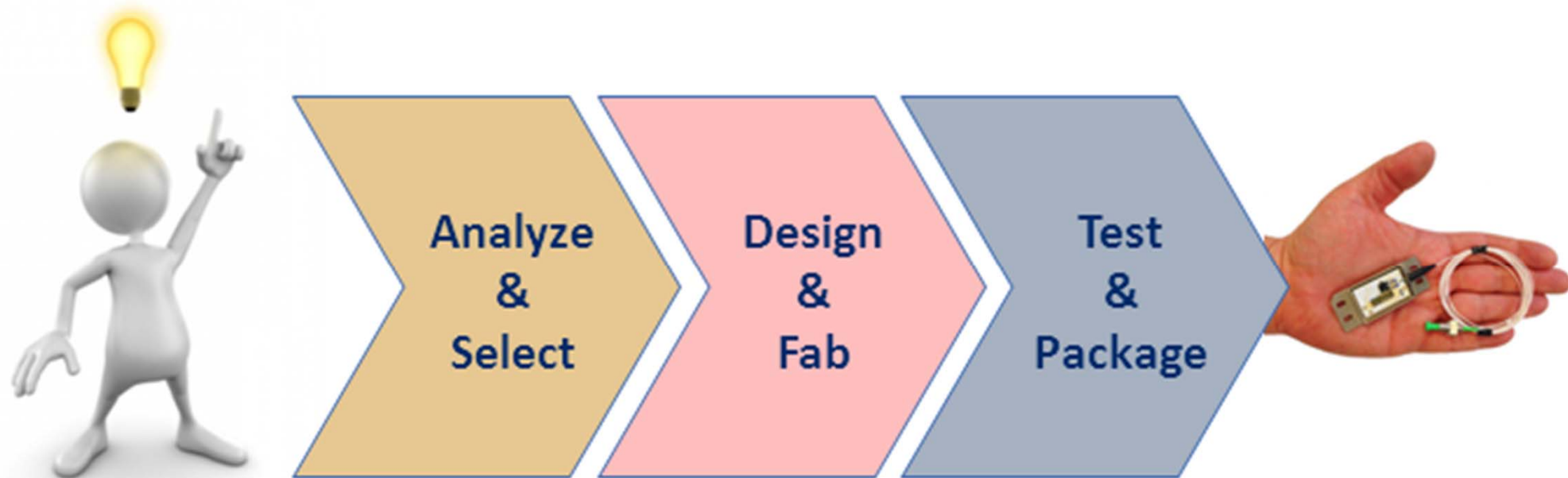
# Full Service Design House

16-Sep-2014



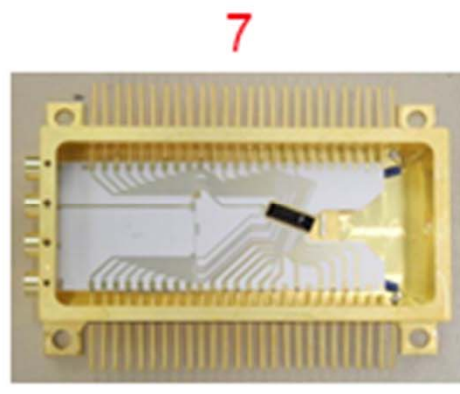
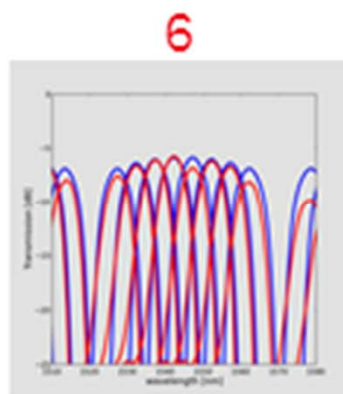
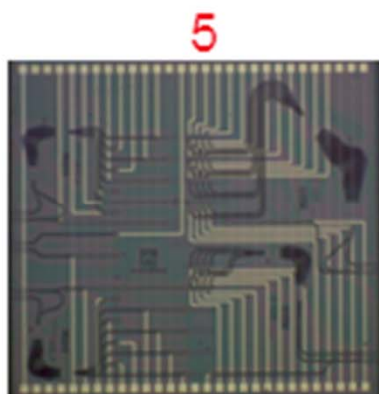
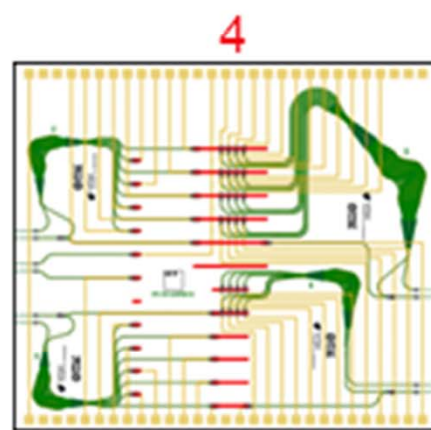
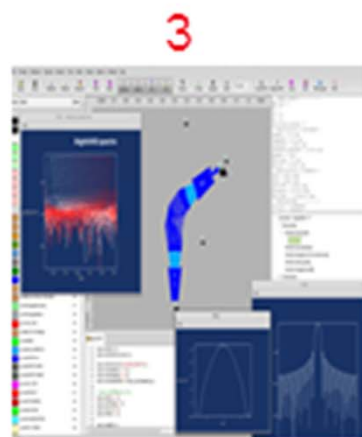
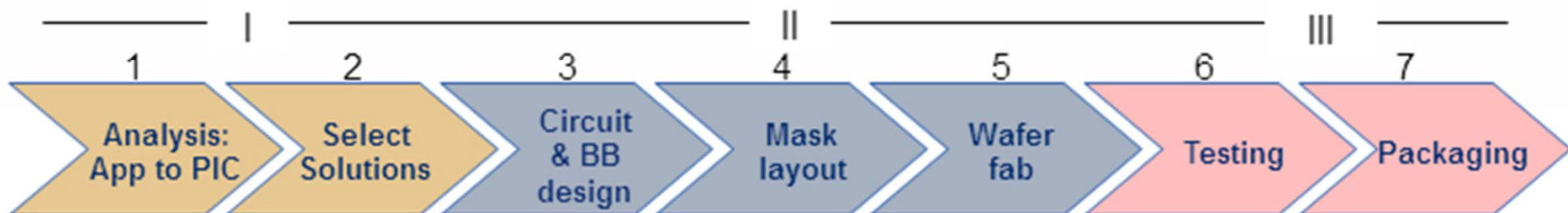
# Design house supports from application idea to PIC prototype

- In 3 phases from idea to packaged PIC





# Design house support 3 phases in 7 steps



# Summary

- Integrated optics is gaining momentum
  - Especially for 100Gbps, but also in many other areas.
- Developing a PIC can still be expensive...
  - MPW brings down the costs & simplifies the process to create a PIC
- Use a detailed automated PDK plus the right design S/W.
- Choosing the right material is tricky, but MPW services are available for the most important material systems.
- All MPW foundries can seamlessly scale from prototype to dedicated (custom) production runs.
- There are a good number of packaging options
- And hopefully with all these efforts together, the field of integrated optics can gain even more momentum.

# Thanks!

[www.7pennies.com](http://www.7pennies.com)





# It's Time for Questions

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You can submit a question using the question tool on your screen.



**Thank you for attending.**

More questions?

Contact:

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